

AFE5851 16-Channel Variable Gain Amplifier (VGA) with Octal High-Speed ADC

The AFE5851EVM is an evaluation tool designed for the ultrasound analog front-end (AFE) device AFE5851. In order to deserialize the outputs of AFE5851, an ADSDeSer-50EVM or TSW1400EVM is needed during the evaluation.

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1 Introduction

The AFE5851 includes an 16-channel Voltage-Controlled-Amplifier (VCA) with digital control and an 8-channel 65MSPS analog-to-digital converter (ADC). The 16 analog input signals will be processed by the analog front-end circuit of AFE5851; the outputs of the analog front-end will then be digitalized by the ADC within the device. There are only eight ADCs within the AFE5851; therefore the odd and even channels are multiplexed into one LVDS output pair. The output of the ADC is streamed out in serial format. In order to process the sample data, the Texas Instruments' TSW1400EVM is recommended. The TSW1400 includes a High-Speed LVDS Deserializer, Demultiplexer, and Analysis System which provide a comprehensive set of hardware and user interface software to effectively evaluate the performance of AFE5851.

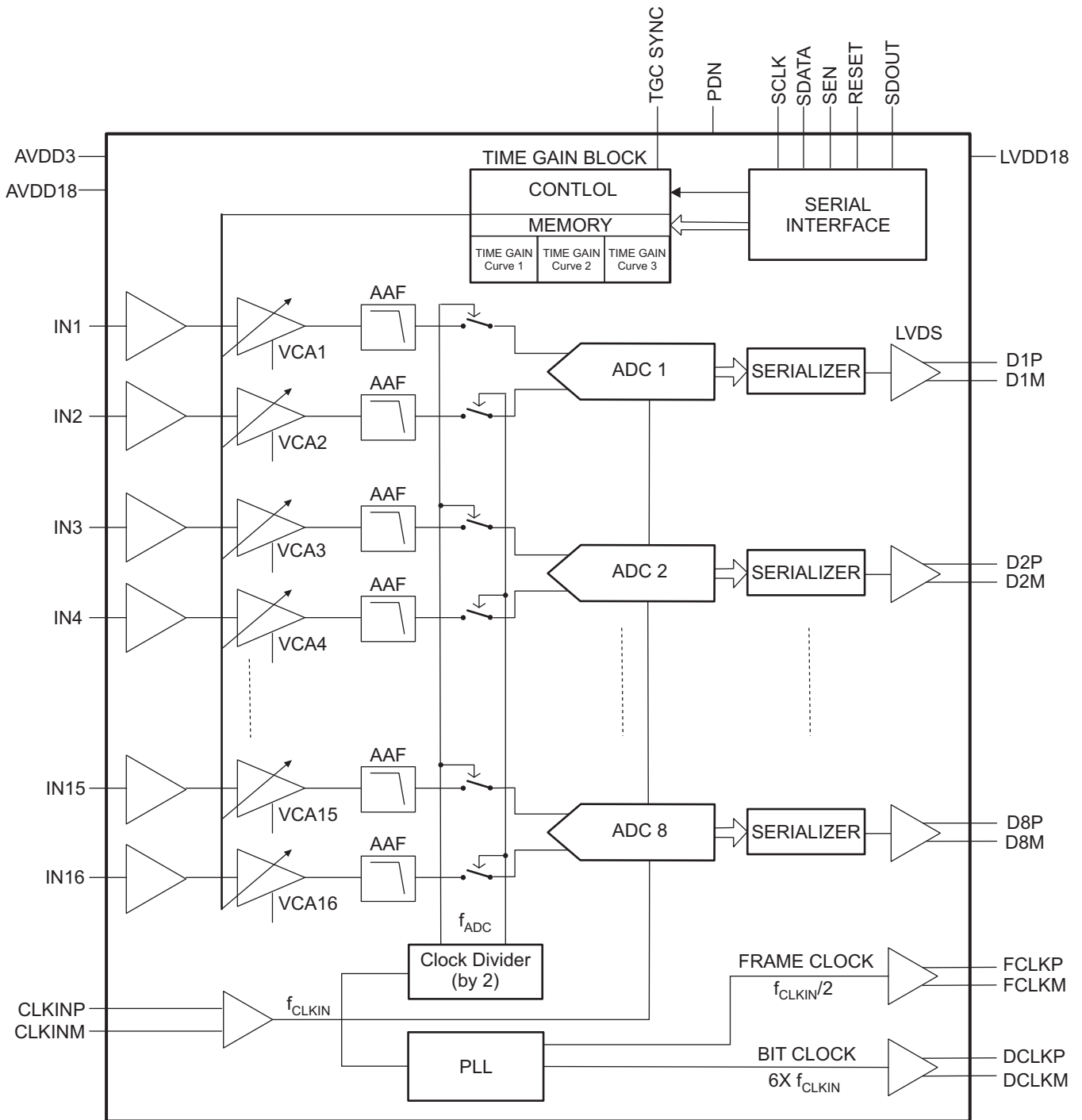


Figure 1. AFE5851 Block Diagram

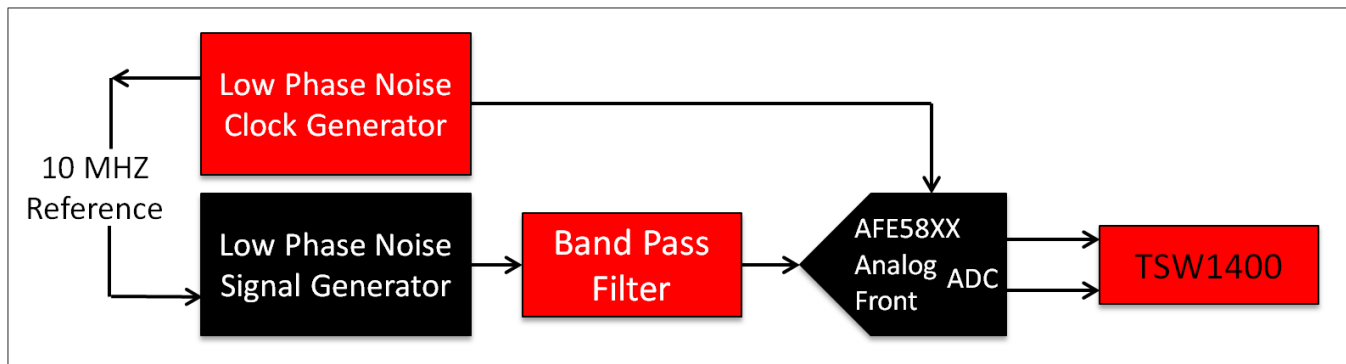


Figure 2. Block Diagram of Test Setup

1.1 AFE5851EVM Kit Contents

The AFE5851EVM kit contains the following:

- AFE5851 EVM board
- USB cable
- AFE/TSW Adapter Bd

1.2 Features

- Characterize AFE5851
- Provide 8-channel low-voltage differential signal (LVDS) outputs from the ADC
- Compatible to the standard TI LVDS deserializer ADSDDeSer-50EVM or TSW1400EVM
- Communicate with PC through USB interface
- Power Management provides multiple power supplies for AFE5851 and other devices.

1.3 Power Supplies

The AFE5851EVM requires only +5V power supplies for operation.

1.4 Indicators

The AFE5851EVM has 4 LEDs on the board as shown in Figure 3. Their states demonstrate the normal operation of AFE5851EVM.

- **LED 1:** U1 status indicator. Its ON state indicates the clock management chip U1 works well if U1 is installed.
- **LED 2:** +3.3V power supply indicator. ON state indicates that the AFE5851 is powered correctly.
- **LED 3 and 4:** 1.8VD and 1.8VA power supply indicators. ON state indicates that the AFE5851 is powered correctly.

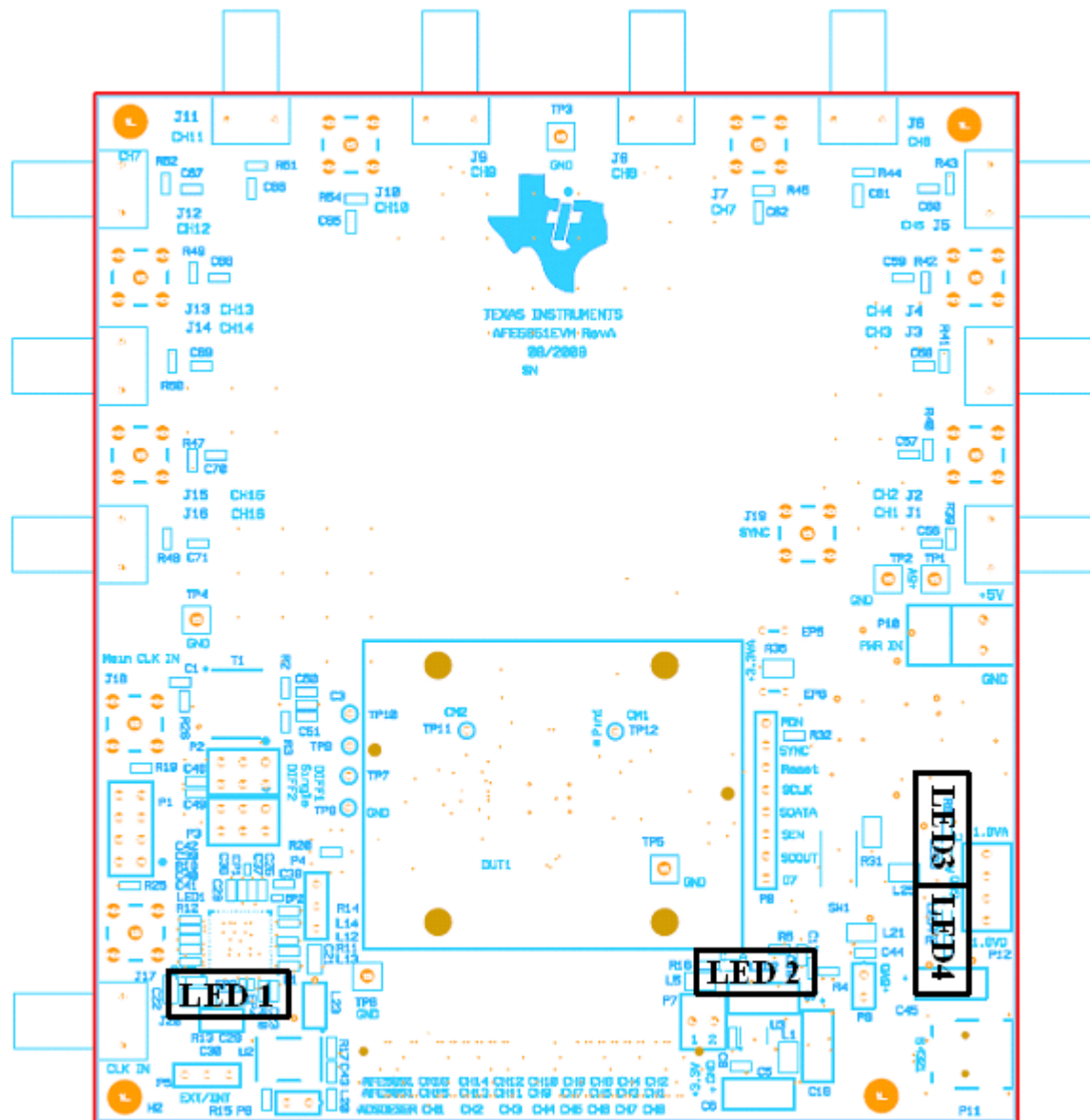


Figure 3. AFE5851EVM LED Locations

2 Board Configuration

This chapter describes the locations and functionalities of inputs, outputs, jumpers, test points of the AFE5851EVM in detail.

2.1 Board Connections Overview

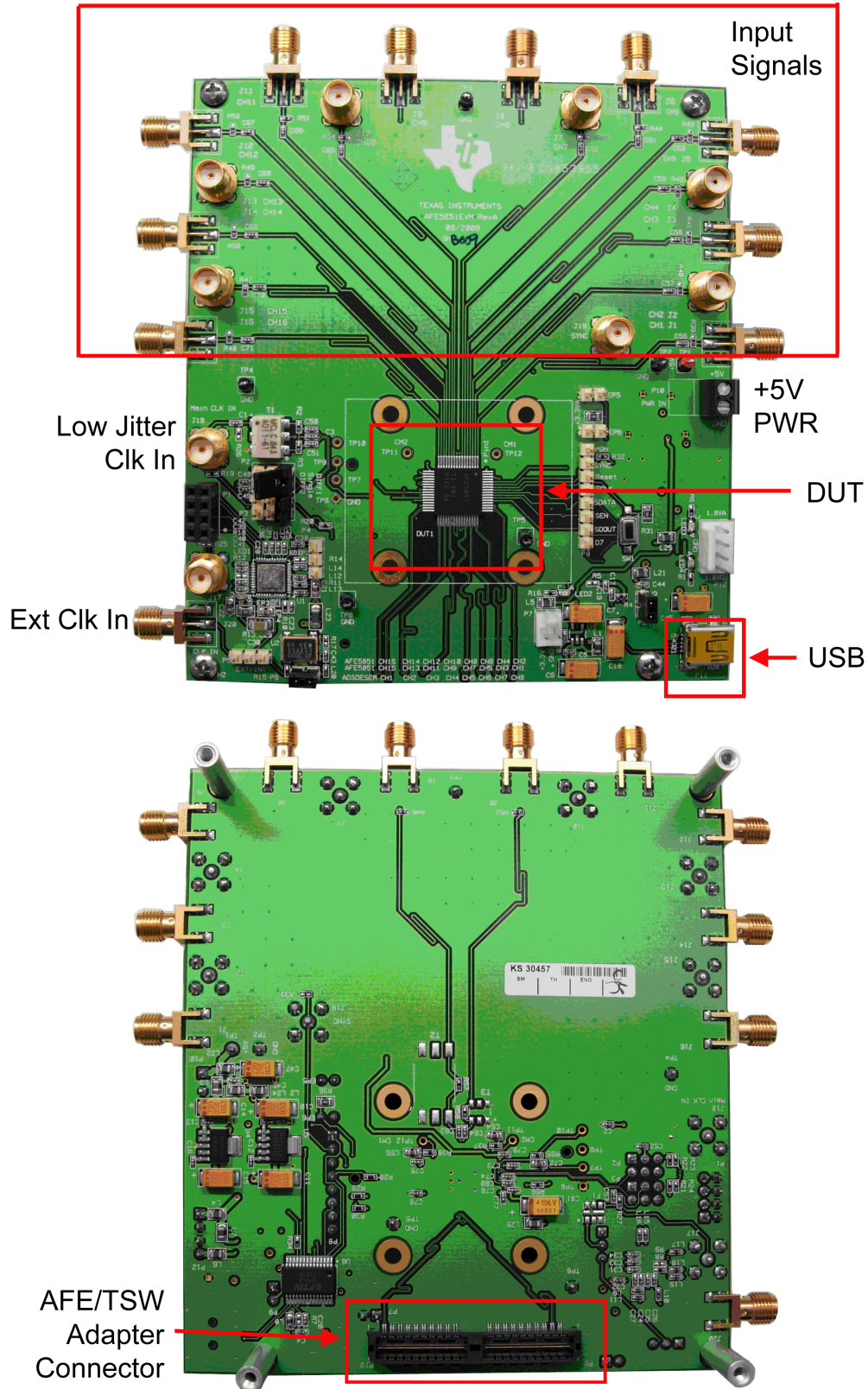


Figure 4. AFE5851EVM Top and Bottom Views

2.2 I/O and Power Connectors

The positions and functions of the AFE5851EVM connectors are discussed in this section.

- Analog Inputs Ch1~Ch16 (J1~J16): Single-end analog signals.
- Low Jitter CLK Source Input (J18): This input accepts clocks with low jitter noise, such as HP8644 output. 20~65MHz 50% duty cycle clock with 1~2Vrms amplitude can be used. When J18 is used, make sure shunt P4,5,6 are removed.
- CLK output (J17): The output of either the U1 output or the on-board 40MHz oscillator output depending on jumper P4's connection.
- External CLK Input (J20): ADC Clock input, such as FPGA outputs. FPGA outputs must be processed by U1. Otherwise, the ADC of AFE5851 will not achieve satisfactory SNR performance.
- +5V PWR connector(P10): Power supply input
- USB input (P11): USB interface to control the AFE5851.
- LVDS Outputs Ch1~Ch8 (P13): Differential LVDS data outputs.

2.3 Jumpers and Setup

The board has been set to default mode. Detailed description can be found in [Figure 5](#) and [Figure 6](#).

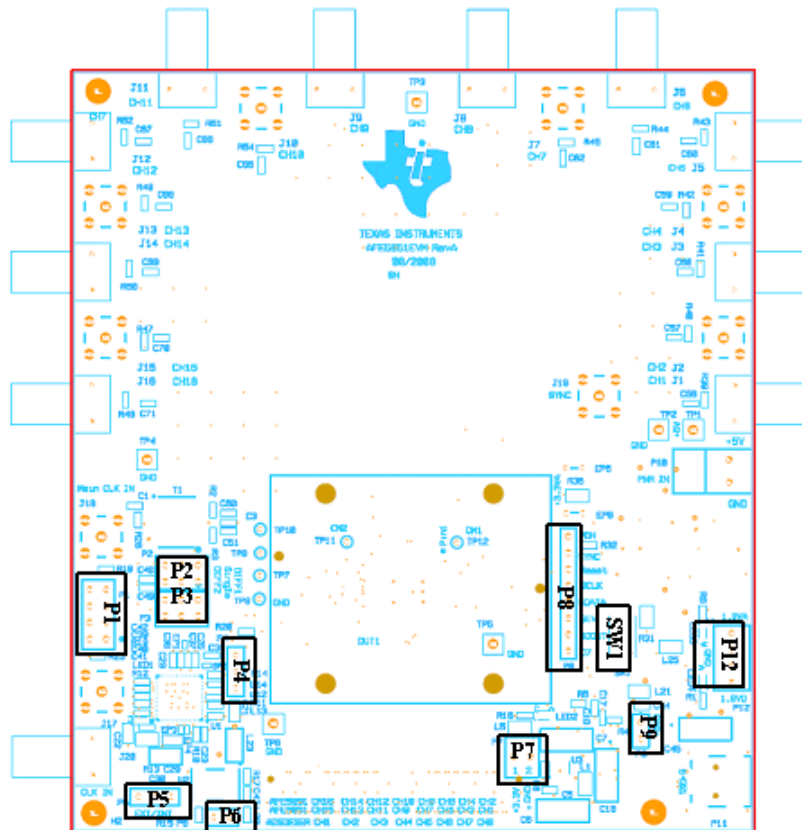


Figure 5. Locations of Jumpers, Headers and Switches on the AFE5851EVM

- P1: SPI interface for U1.
- P2, P3: AFE5851 ADC clock input selection: transformer-based differential clock, single-ended LVCMOS clock, or future clock option (needs U1 to support). Default is to use transformer-based differential clock.
- P4: Select jitter-cleaned clock or non-jitter-cleaned clock. Default is to use non-jitter-cleaned clock (i.e., on-board 40MHz clock).
- P5: Use on-board 40MHz clock. Default is that on-board clock is used.

- P6: Power on on-board 40MHz clock generator. Default is on.
- P8: Debug port for monitoring ADS SPI signals.
- P9: USB interface enable. Default is on.
- Regulated power supply outputs (P12, P7): 1.8VA, 1.8VD, and 3.3V. P12 and P7 can be configured as power supply input as well if users would like to skip on board regulators. Remove the ferrite bead L1, L2, L3, L7 and L24,
- SW1: Reset switch for AFE5851.

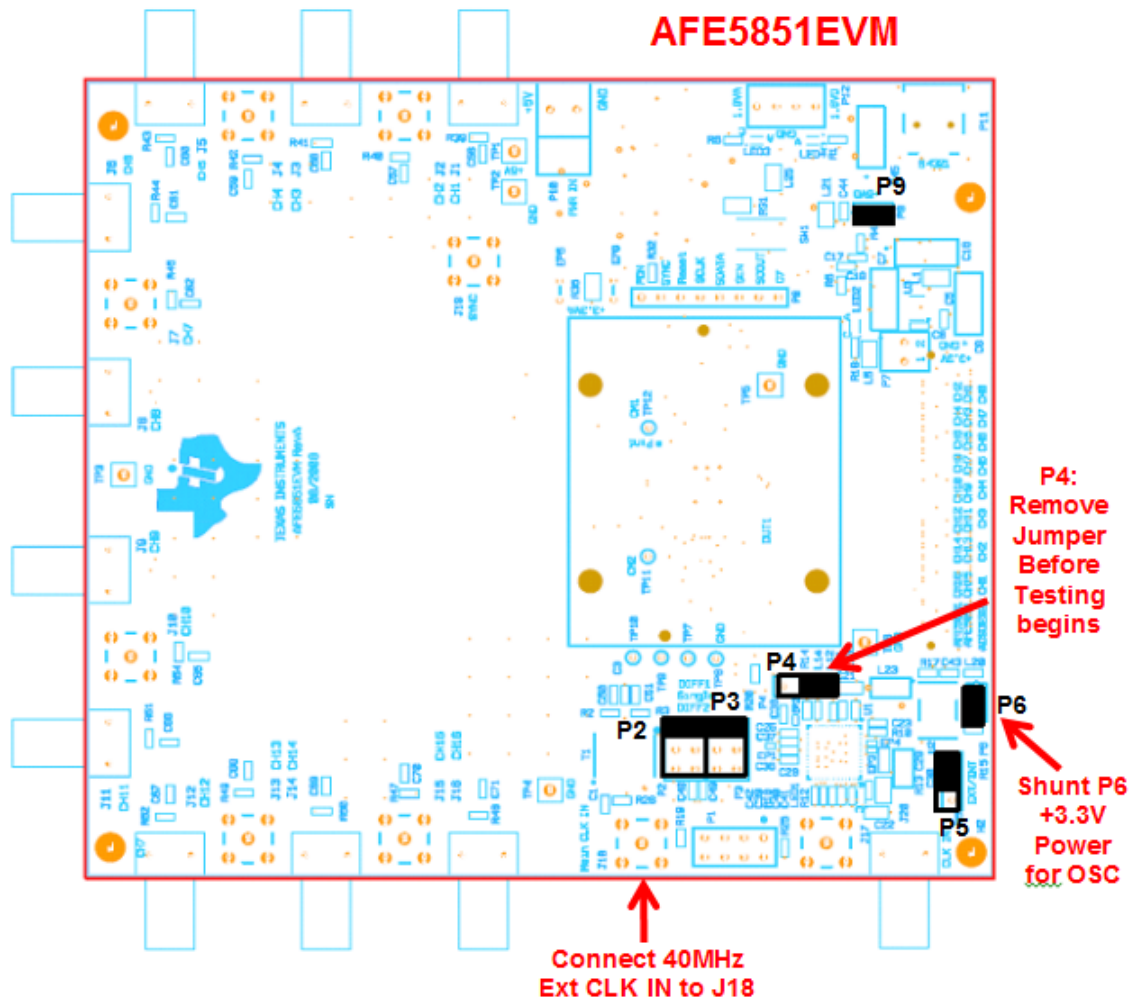


Figure 6. Default Setup for Jumpers

2.4 Test Points

- Multiple Test Points are provided on the EVM. Refer to the [Schematics Section](#) for more information.

3 Board Operation

This chapter describes how to operate the AFE5851EVM for evaluation. Both software and hardware installation and operation are discussed.

3.1 Software Installation and Operation

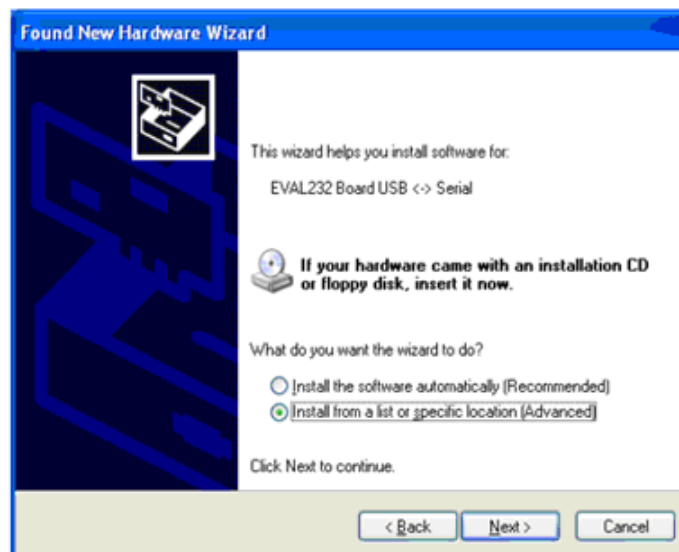
The AFE5851EVM comes with a software install. To Download the software, visit the AFE5851 [product folder](#) and select *Tools & software* . Once the zip folder is downloaded, run setup.exe to install the software. The software to use the TSW1400EVM is called HSDCPro (High Speed Data Converter Pro). For information on how to download this software, please see [Appendix B](#).

3.2 USB Driver Installation

- Connect the USB port of EVM to your PC.
- If the driver has not been installed then the message “Window Found New Hardware” will appear. The Wizard as the following picture will launch.
- Select "No, not this time" from the options. Press Next button



- Select "Install from a list or specific location (Advanced)" as shown below and then click "Next".



- Select "Search for the best driver in these locations" and enter the file path for ("C:\Program Files\AFE5851\CDM2.04.06 WHQL Certified") in the combo-box or browse to it by clicking the browse button. Once the file path has been entered in the box, click next to proceed.
- If Windows XP is configured to warn when unsigned (non-WHQL certified) drivers are about to be

installed, the following screen will be displayed unless installing a Microsoft WHQL certified Driver. Click on "Continue Anyway" to continue with the installation. If Windows XP is configured to ignore file signature warnings, no message will appear.



Different modes exist as shown in [Figure 7](#) through [Figure 9](#).

When AFE5851EVM is powered on, all registers have been set to their default modes. Refer to the data sheet for all default settings. It is recommended to restart the SPI software when AFE5851 is powered on in order to synchronize the AFE5851 register settings to the software displays.

Users also can fill out Address Bytes and Data Bytes and press *ENTER* to configure each register.

Initial measurements can be made after the EVM is powered and the fixed gain mode is selected.

The software also allows users to configure the AFE5851 as 8-channel mode or 16-channel mode. Corresponding LVDS deserializing algorithms are needed respectively.

3.3 GUI Startup

Launch GUI from XP Window

Start → All Programs\AFE5851EVM\AFE5851

[Figure 7](#) through [Figure 9](#) show several screen images of the different modes.

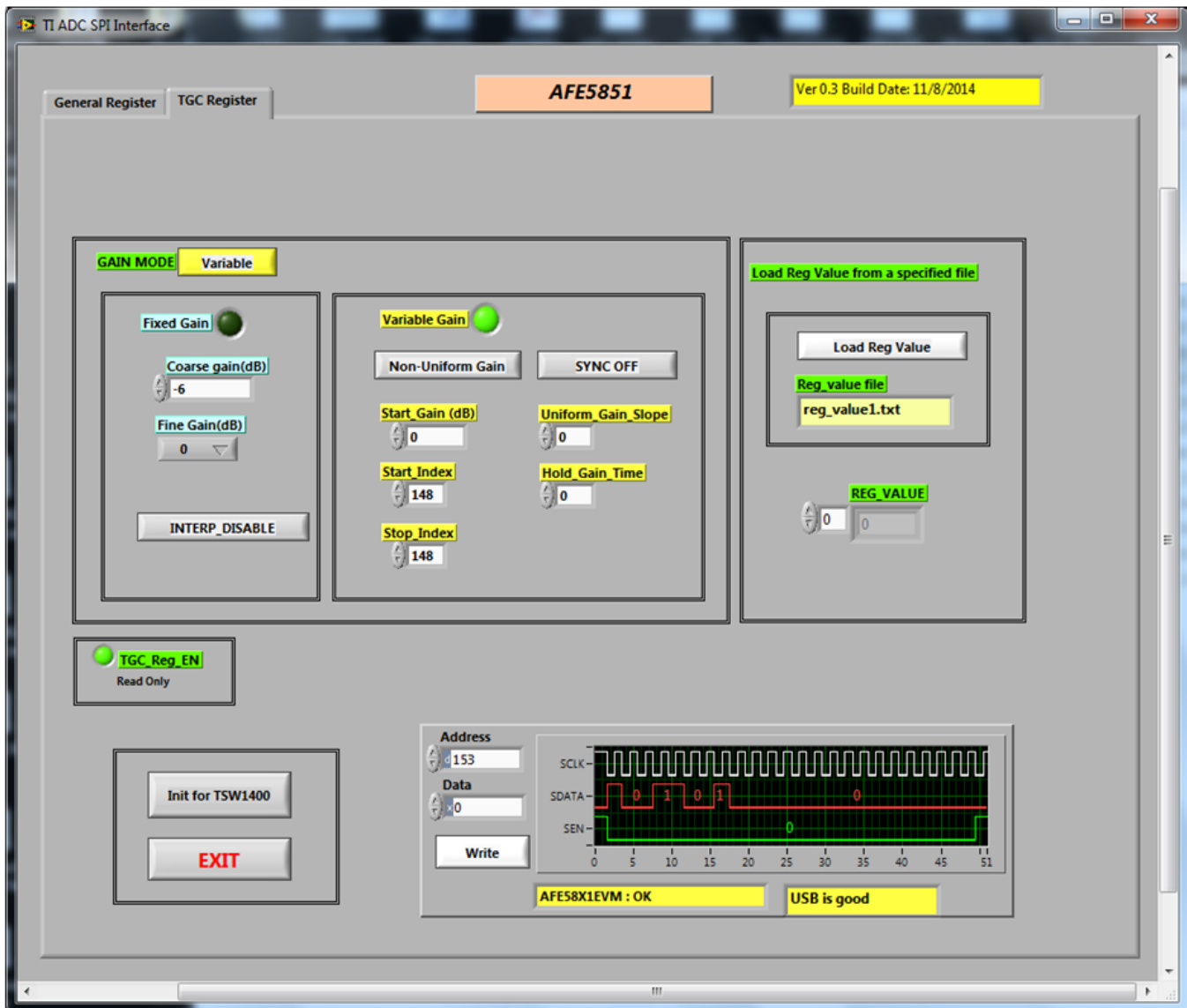


Figure 7. AFE5851EVM USB SPI Interface for General Registers

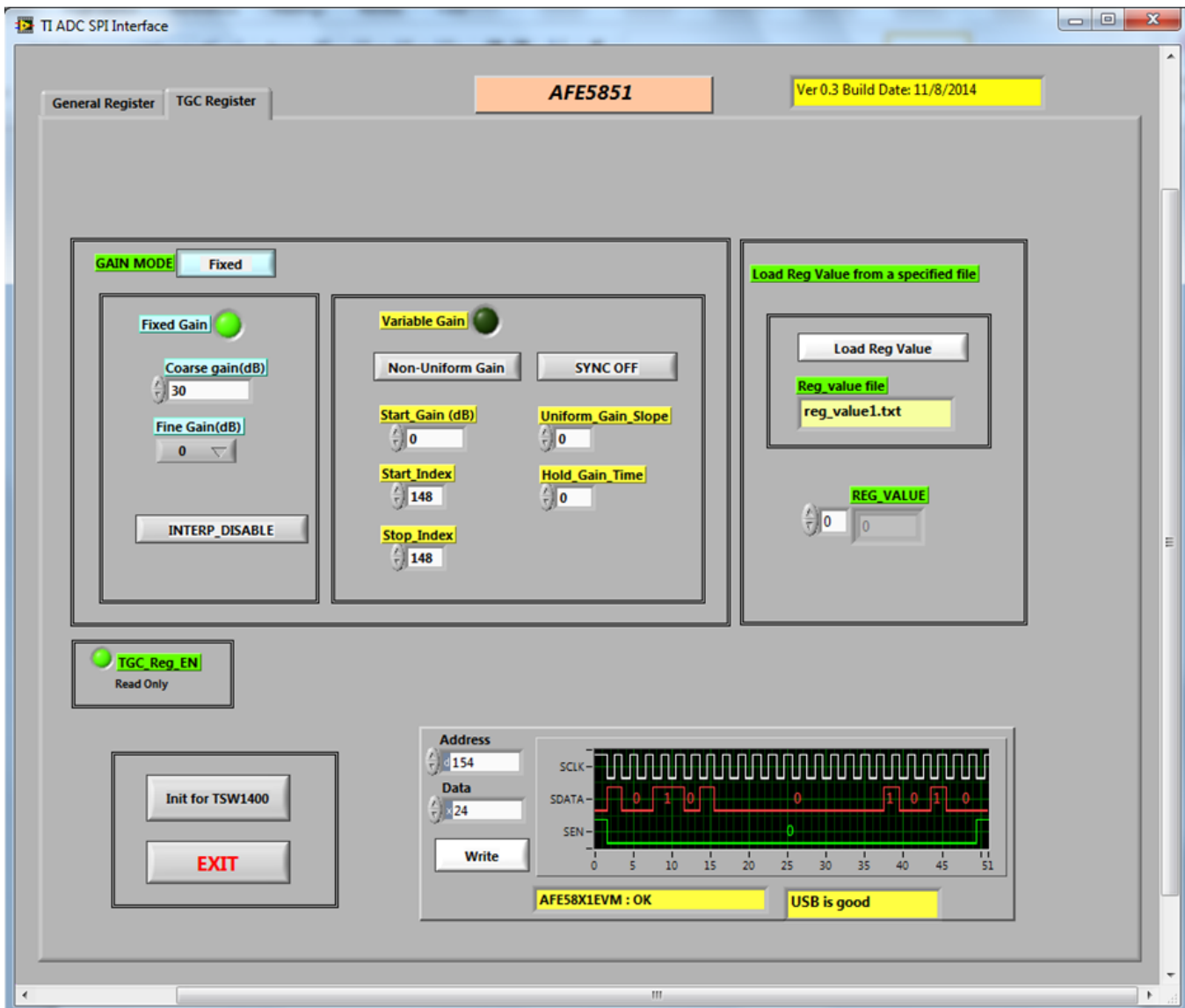


Figure 8. AFE5851EVM USB SPI Fixed Gain Mode

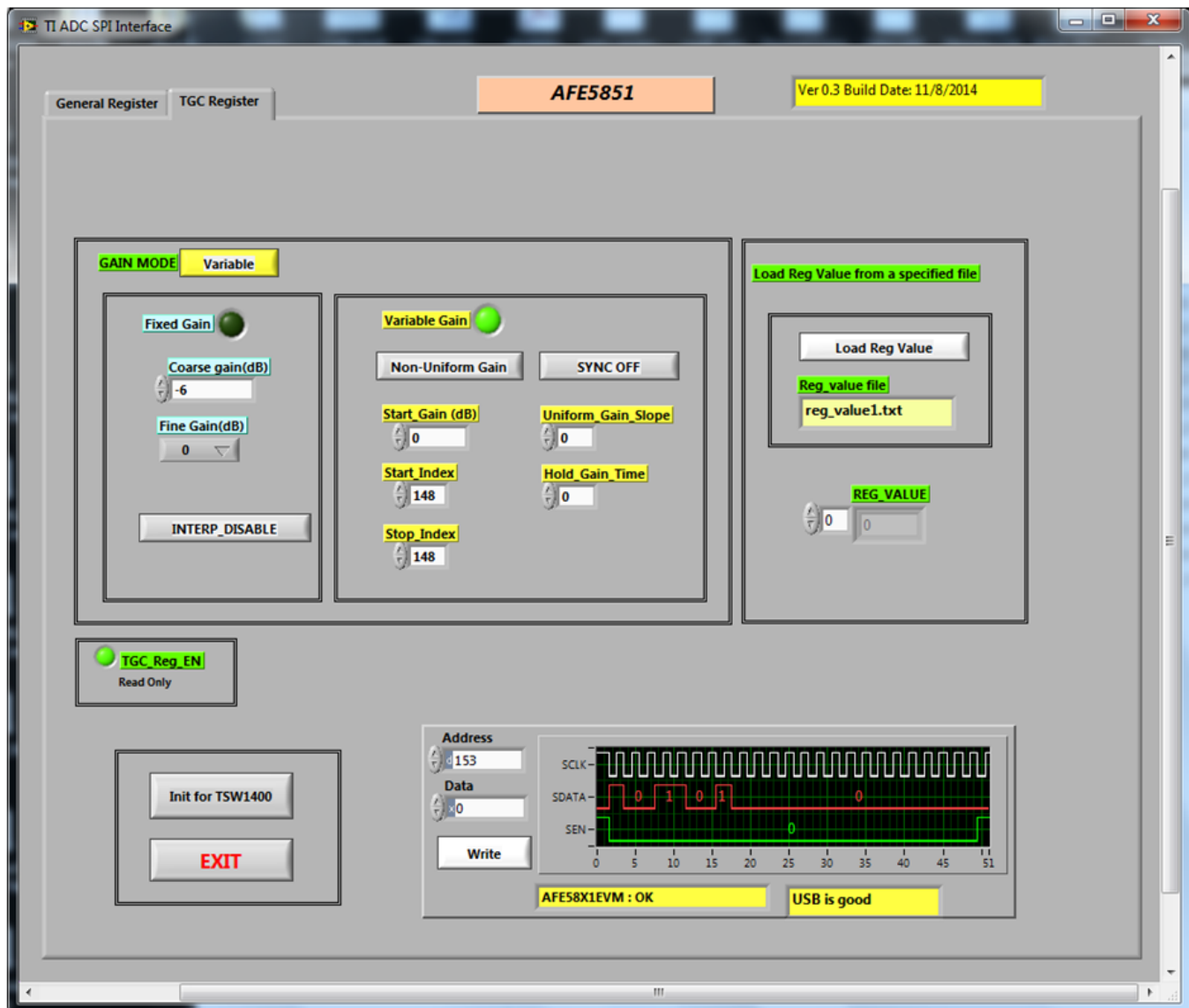


Figure 9. AFE5851EVM USB SPI Interface for Variable Gain Mode

When AFE5851EVM is powered on, all registers have been set to their default modes. Please refer to the datasheet for all default settings. It is recommended to restart the SPI software when AFE5851 is powered on in order to synchronize the AFE5851 register settings to the software displays.

Users also can fill out Address Bytes and Data Bytes and press "ENTER" to configure each register.

Typical Configuration

- From [Figure 7](#) press "Init for TSW1400" button.
- Select TAB "TGC Register" — [Figure 9](#) will appear.
- From [Figure 9](#) press "Variable" toggle button to enter fixed gain mode.
- From [Figure 8](#) enter 30 in the "Coarse Gain(dB)" field, then press "Write" button.

3.4 Hardware Setup

As mentioned before, Xilinx DeSerializer ADSDeSER-50EVM or TSW1400EVM is required. See details in the corresponding application notes on how to use either of these EVMs. An example bench setup is shown in Figure 10. Band-pass filters are required for signal source in order to ensure the correct SNR measurements of the AFE5851.

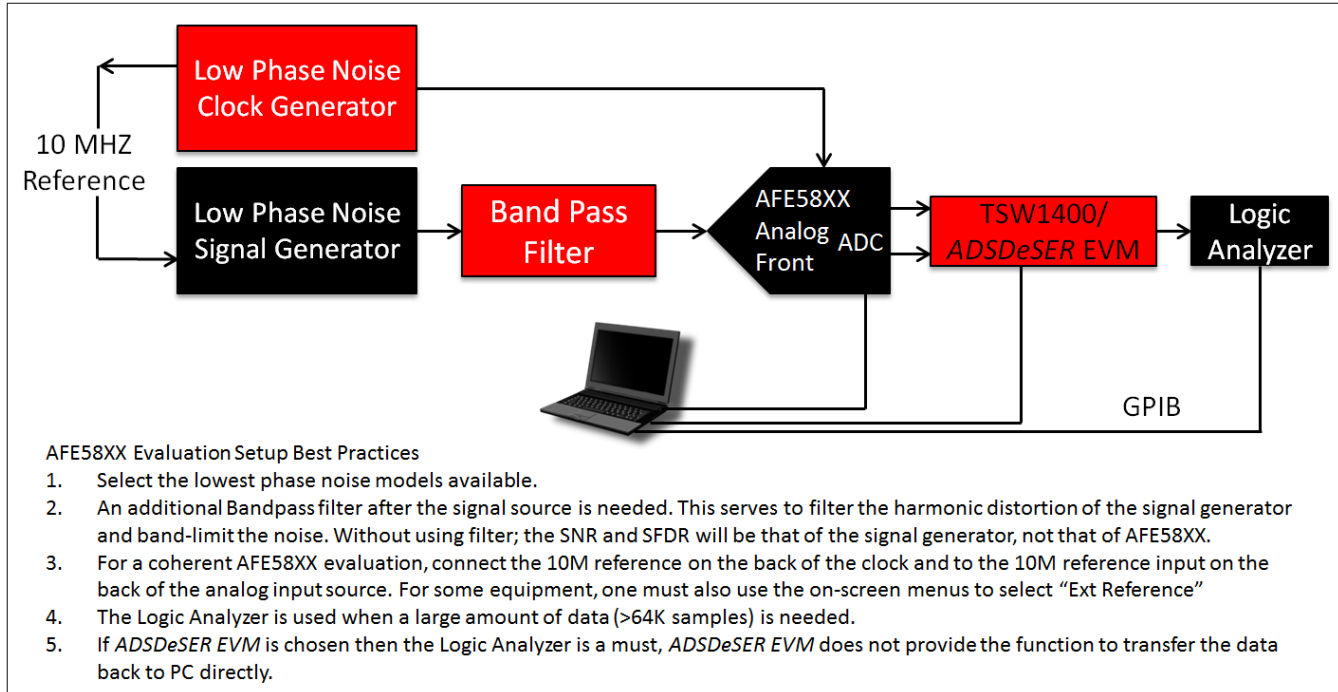


Figure 10. Typical AFE5851 Bench Setup

The channel order of the AFE5851 outputs is not exactly the same as the order of the ADS527x outputs. As a result, the channel number on the ADSDeSER-50EVM or AFE5851EVM might be misleading. Table 1 provides channel to channel sequence matching between the ADSDeSER-50EVM and AFE5851EVM.

Table 1. Channel to Channel Matching Between the AFE5851EVM and ADSDeSER-50EVM

| (a) 16-CHANNEL MODE | | | | | | | | | | |
|---------------------|------|-----|-----|-----|-----|------|------|------|------|------|
| AFE | FCLK | CH1 | CH3 | CH5 | CH7 | CH9 | CH11 | CH13 | CH15 | LCLK |
| AFE | FCLK | CH2 | CH4 | CH6 | CH8 | CH10 | CH12 | CH14 | CH16 | LCLK |
| Xilinx | FCLK | CH8 | CH7 | CH6 | CH5 | CH4 | CH3 | CH2 | CH1 | LCLK |
| (b) 8-CHANNEL MODE | | | | | | | | | | |
| AFE | FCLK | CH1 | CH3 | CH5 | CH7 | CH9 | CH11 | CH13 | CH15 | LCLK |
| Xilinx | FCLK | CH8 | CH7 | CH6 | CH5 | CH4 | CH3 | CH2 | CH1 | LCLK |

For example, when an analog signal is input at CH1 on the AFE5851EVM, the corresponding 12-bit digital output will be seen at CH8 on the ADSDeSER-50EVM when the AFE5851 is configured as 8-channel mode.

Current standard ADSDeSER-50EVM can be used to deserialize the AFE5851 LVDS outputs when the AFE5851 is configured as 8-channel mode. ADSDeSER-50EVM deserialization code for the 16-channel mode is available from the AFE5851EVM CD. Programming the ADSDeSER-50EVM with a JTAG cable is necessary.

3.5 Clock Selection

AFE5851 is typically clocked through a transformer-based circuit. Other options are also available if needed as shown in [Figure 11](#).



Figure 11. Clock selection jumper configurations:
(a) Transformer (default); (b) Single-ended clock; (c) Future CLK input option based on U1.
 Both (b) and (c) configurations need some modifications on the PCB.

The clock source of the EVM could be the on-board clock 40MHz, HP8644 low jitter clock source, or external clock source. The best performance of this EVM is achieved when low-jitter clock source HP8644 is used. The P4, P5, P6 should be removed in order to disable the on-board clock.

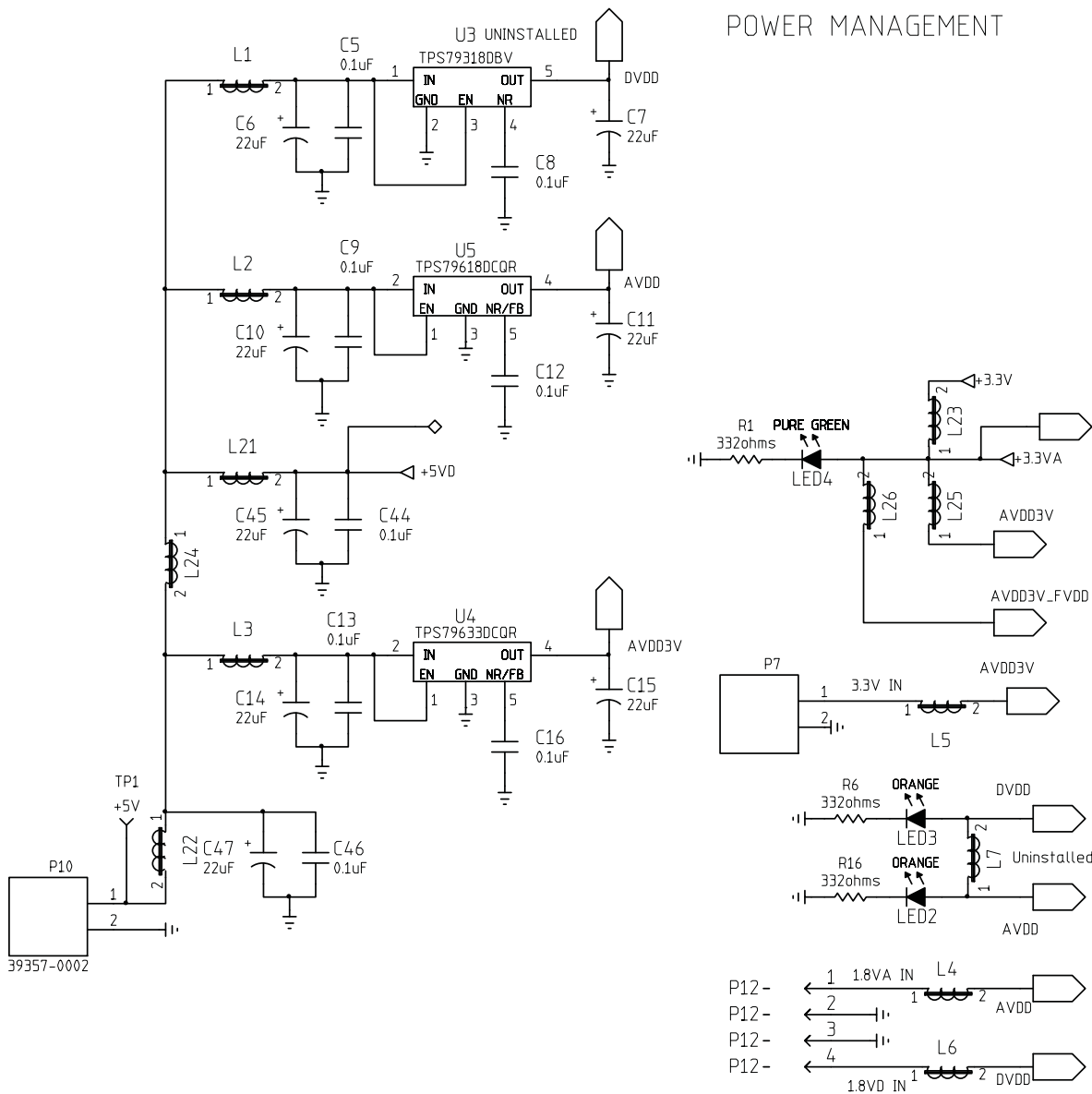
When HP8644 or similar clock sources are not available, the on-board 40MHz clock is also a desirable source. The jumpers P4, 5, 6 should be configured as [Figure 11](#) shows (i.e., default setup for AFE5851EVM). In this mode, the transform-based differential clock is used.

3.6 Data Analysis

Based on the data file acquired by a logic analyzer, the performance of AFE5851 can be evaluated.

Appendix A provides a solution that allows the user to test the performance of all 16 channels using the TSW1400 EVM to deserialize the AFE5851 outputs and process the FFT algorithms to produce the spectral analysis plots via the PC.

When the AFE5851 is configured as an 8-channel device and standard ADSDer-50EVM is used, all samples are needed. However, when the AFE5851 is configured as a 16-channel device and non-standard ADSDer-50EVM code is used, even samples and odd samples are corresponding to CHx and CHx+1 respectively. Please refer to the AFE5851 data sheet for more information on LVDS timing.



POWER MANAGEMENT

Figure 13. Schematic Page 2

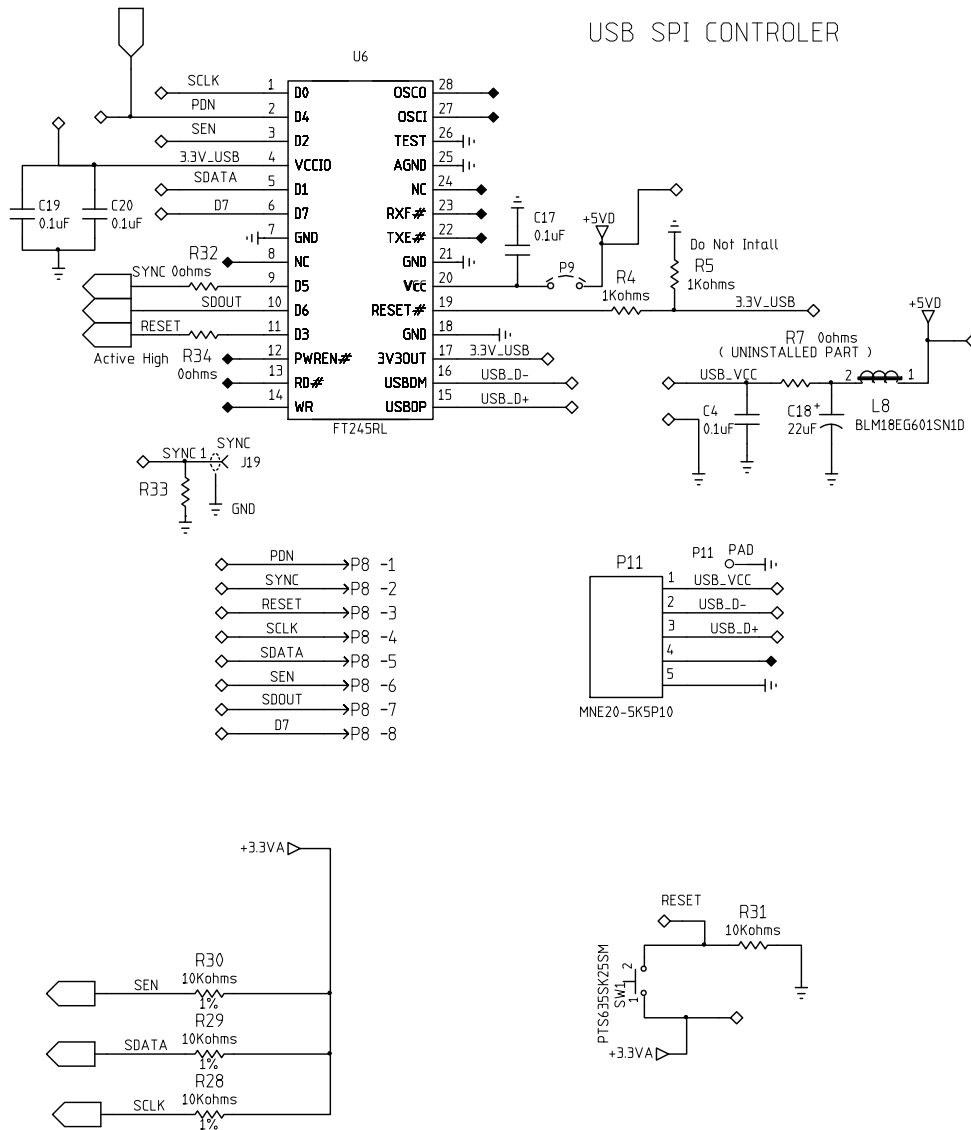


Figure 14. Schematic Page 3

INPUT CHANNELS

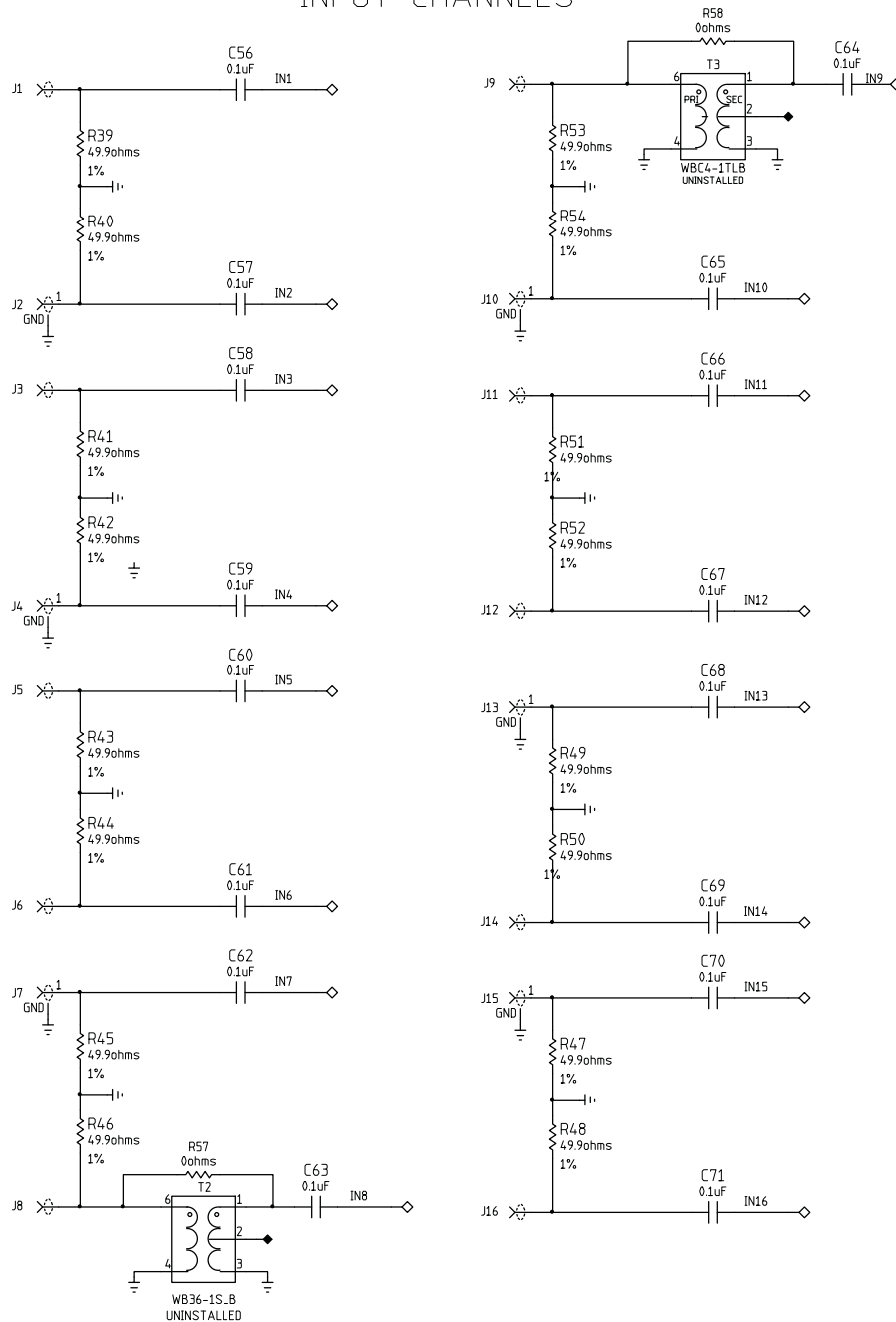


Figure 15. Schematic Page 4

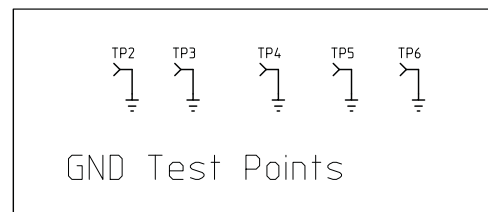
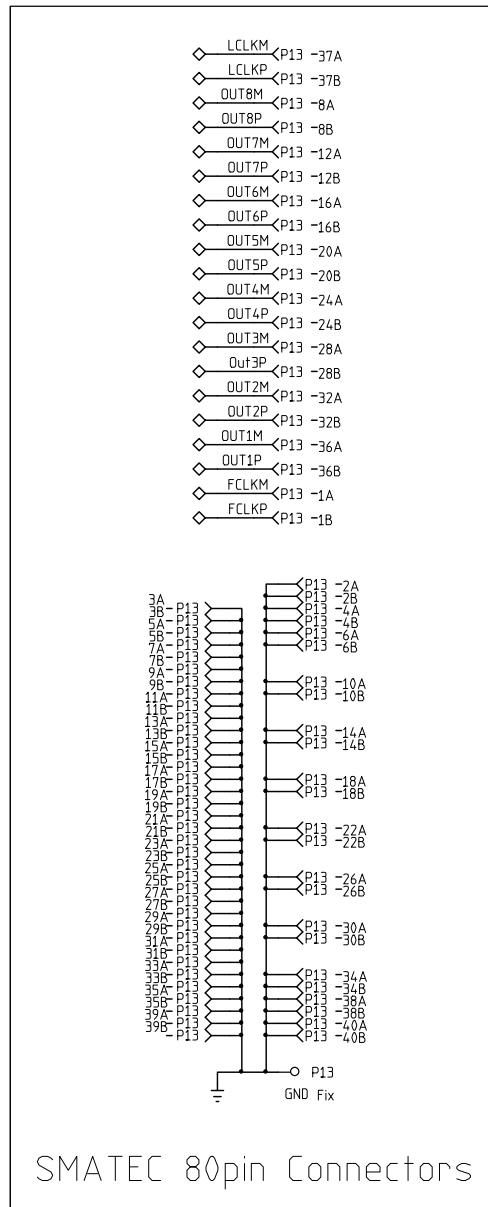
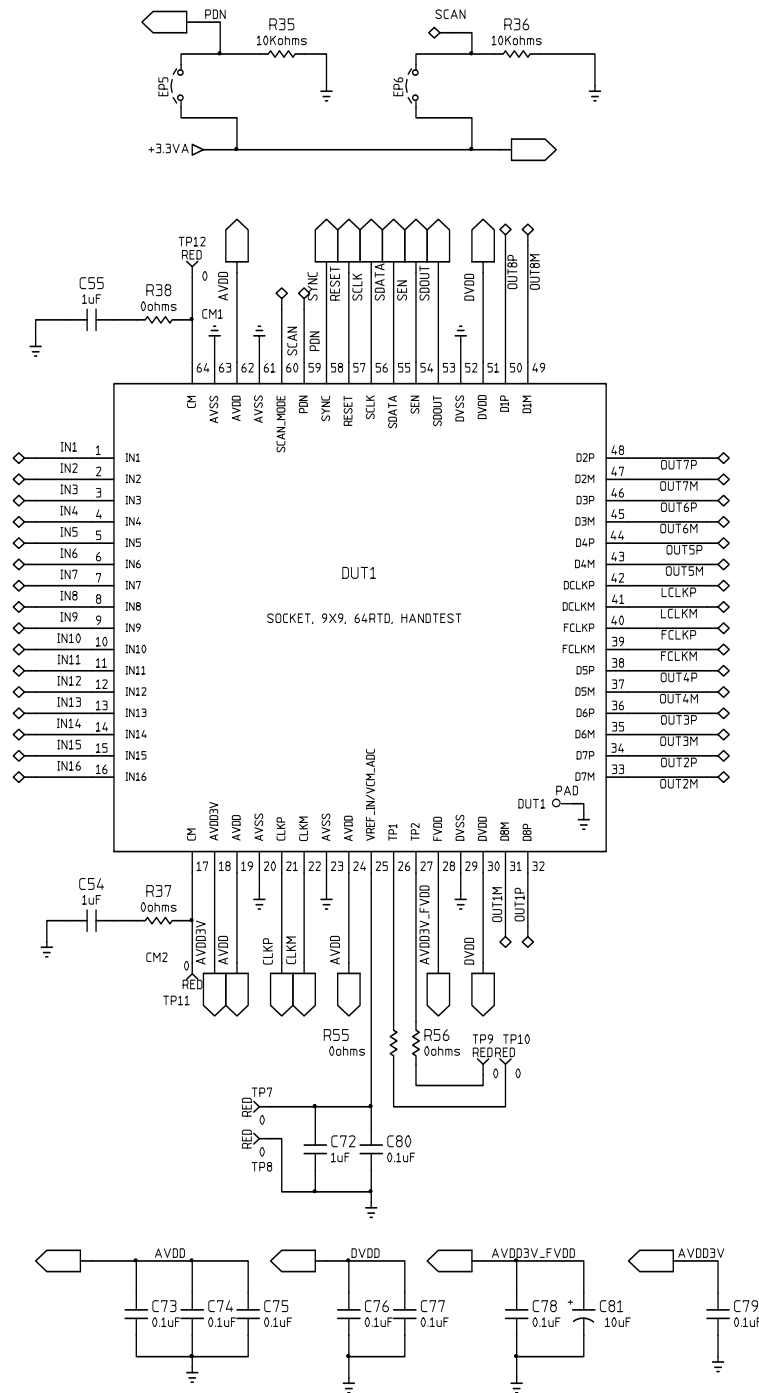


Figure 16. Schematic Page 5



DE-CAPS

Figure 17. Schematic Page 6

4.2 PCB Layout

A six-layer printed-circuit board is used:

- Top Layer, signal
- Inner Layer 1, ground
- Inner Layer 2, signal
- Inner Layer 3, power
- Inner Layer 4, ground
- Bottom Layer, signal
- Top Silk Screen Layer
- Bottom Silk Screen Layer

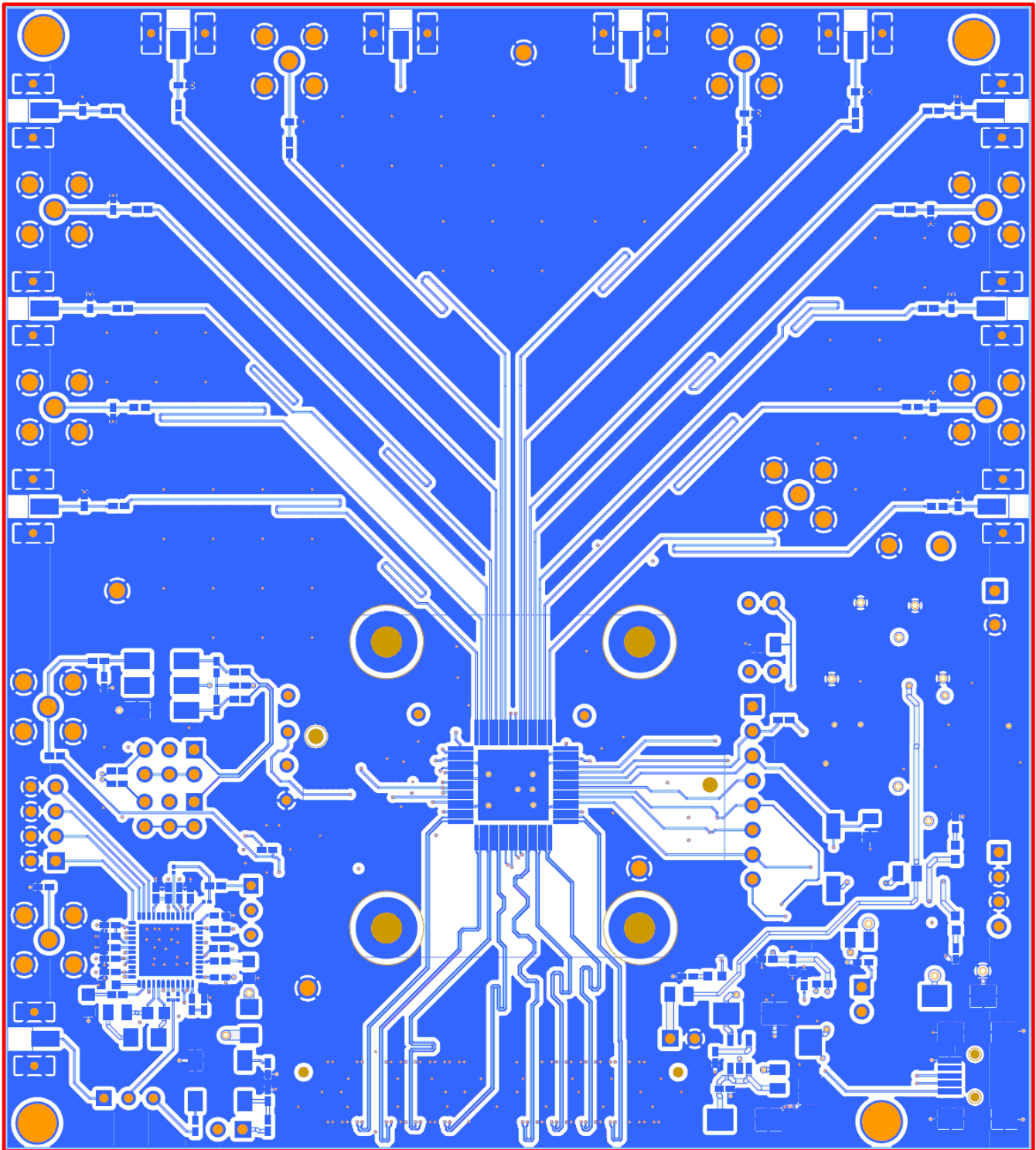


Figure 18. Top Layer – Signal

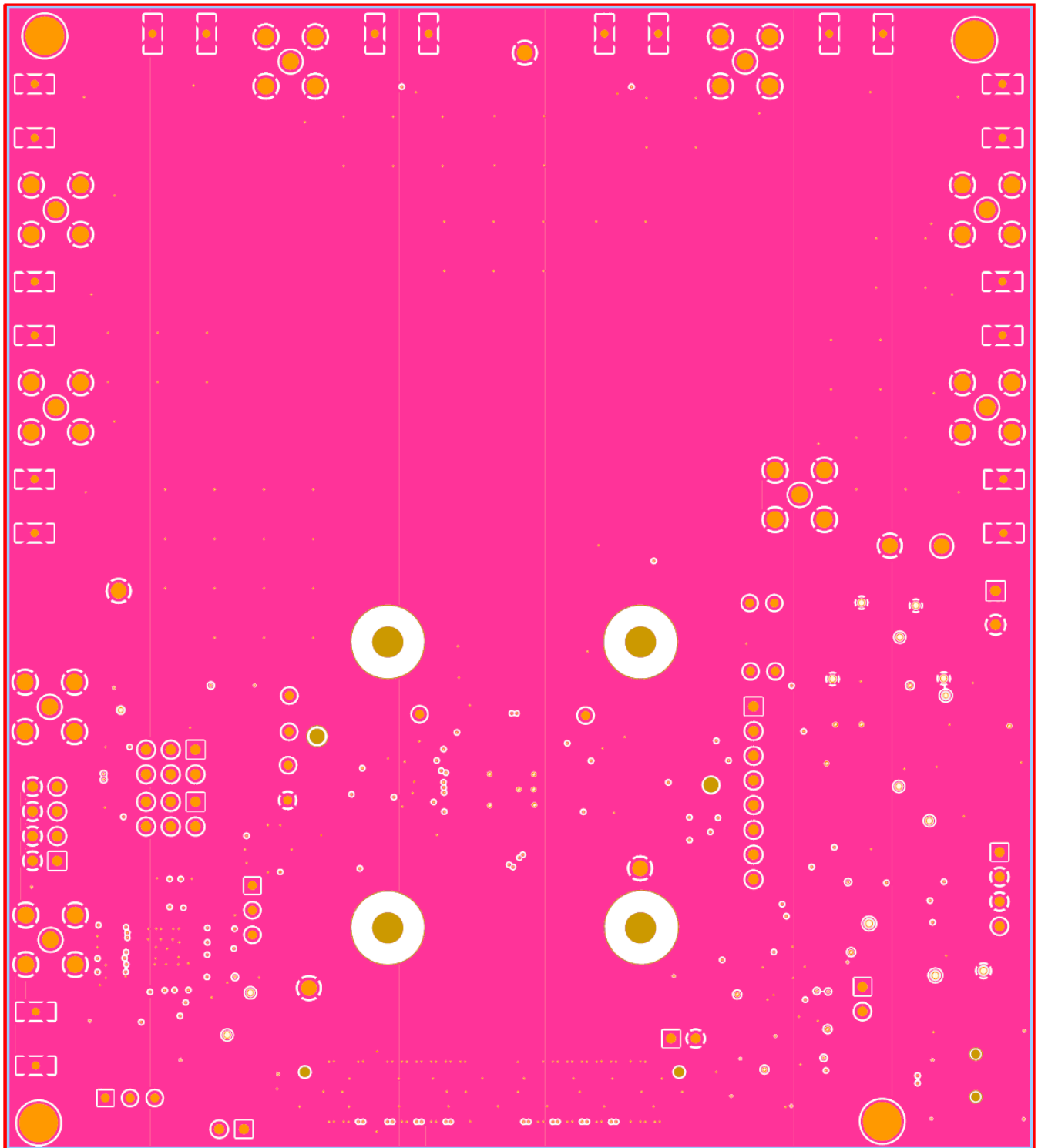


Figure 19. Inner Layer 1 – Ground

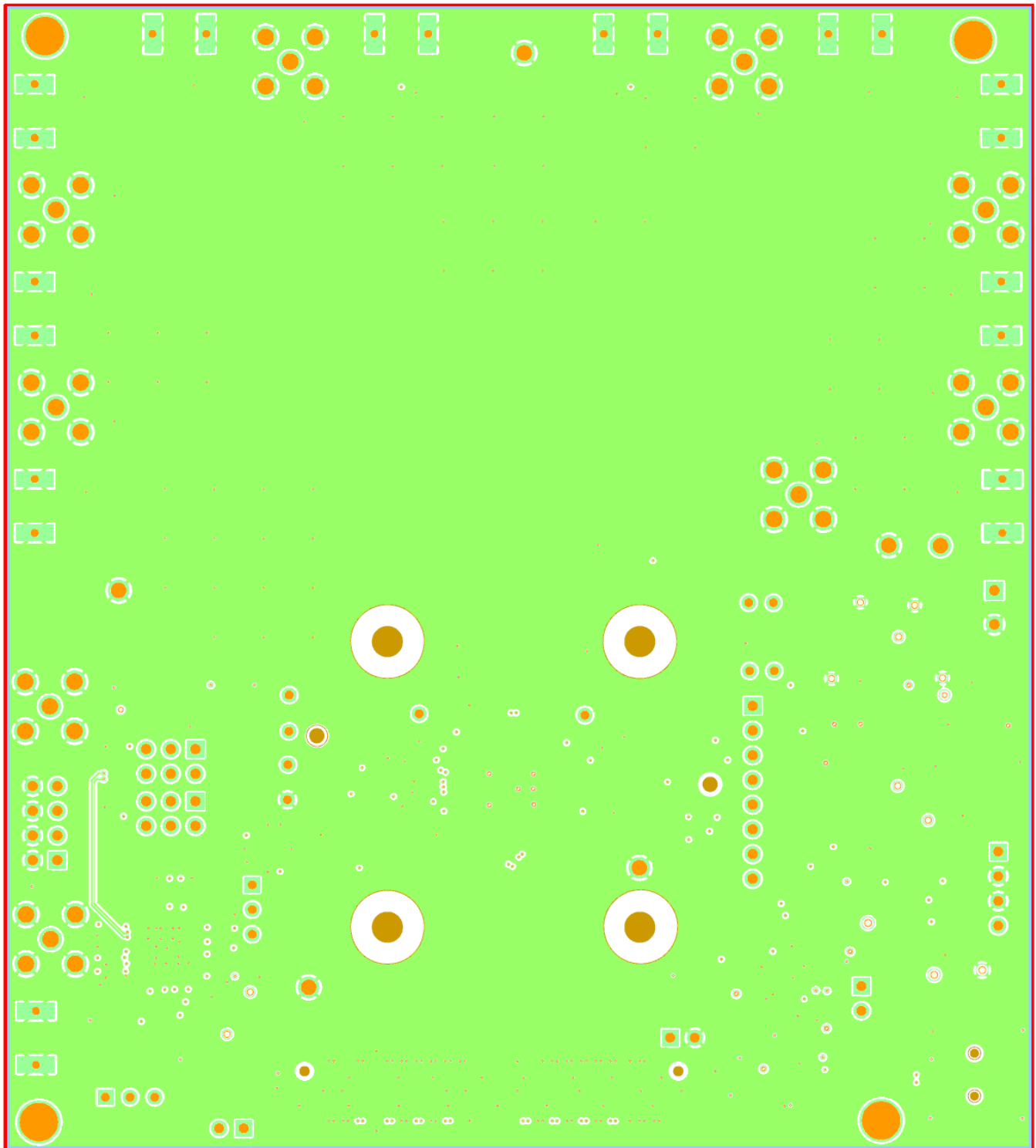


Figure 20. Inner Layer 2 – Signal

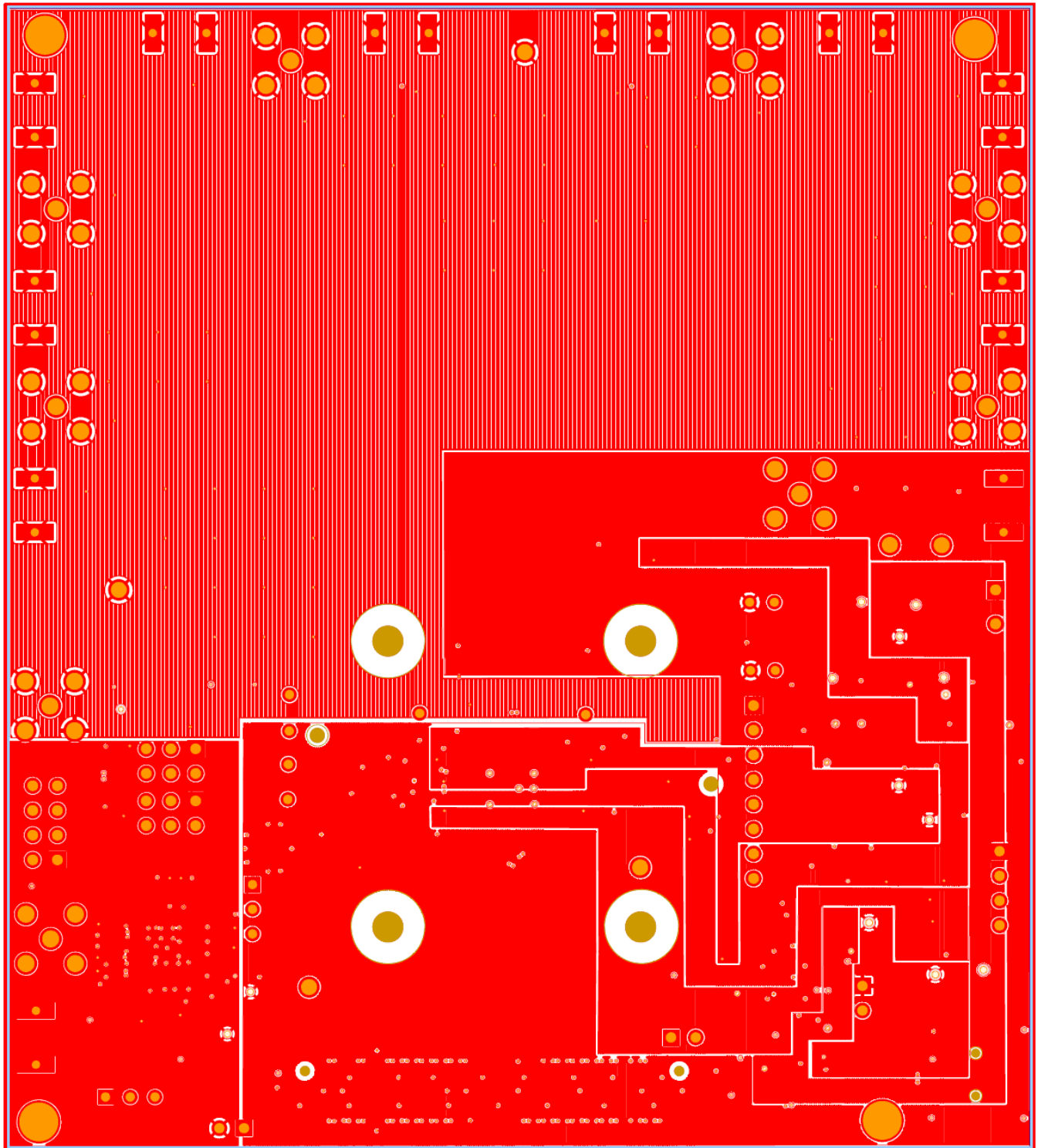


Figure 21. Inner Layer 3 – Power

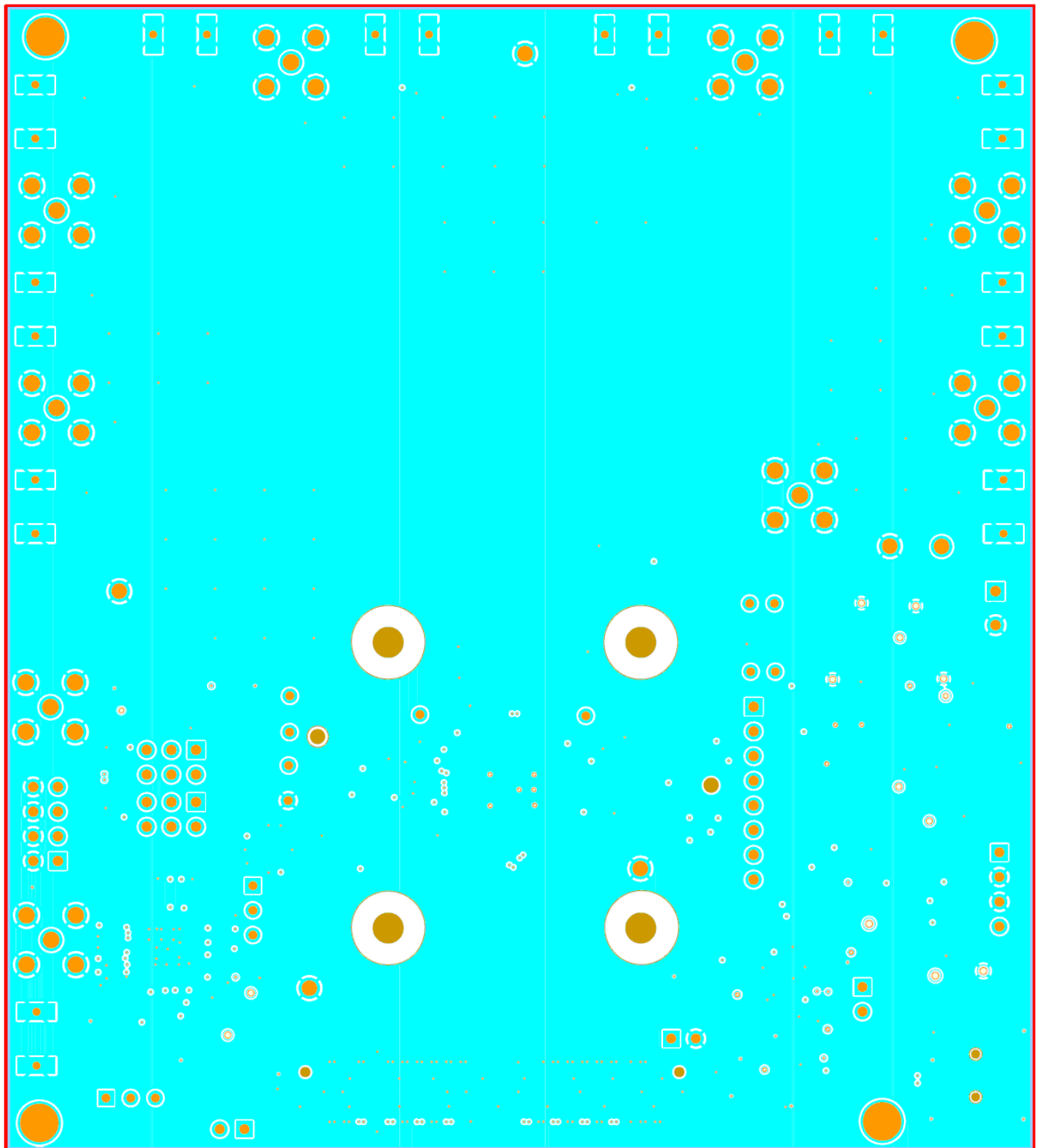


Figure 22. Inner Layer 4 – Ground

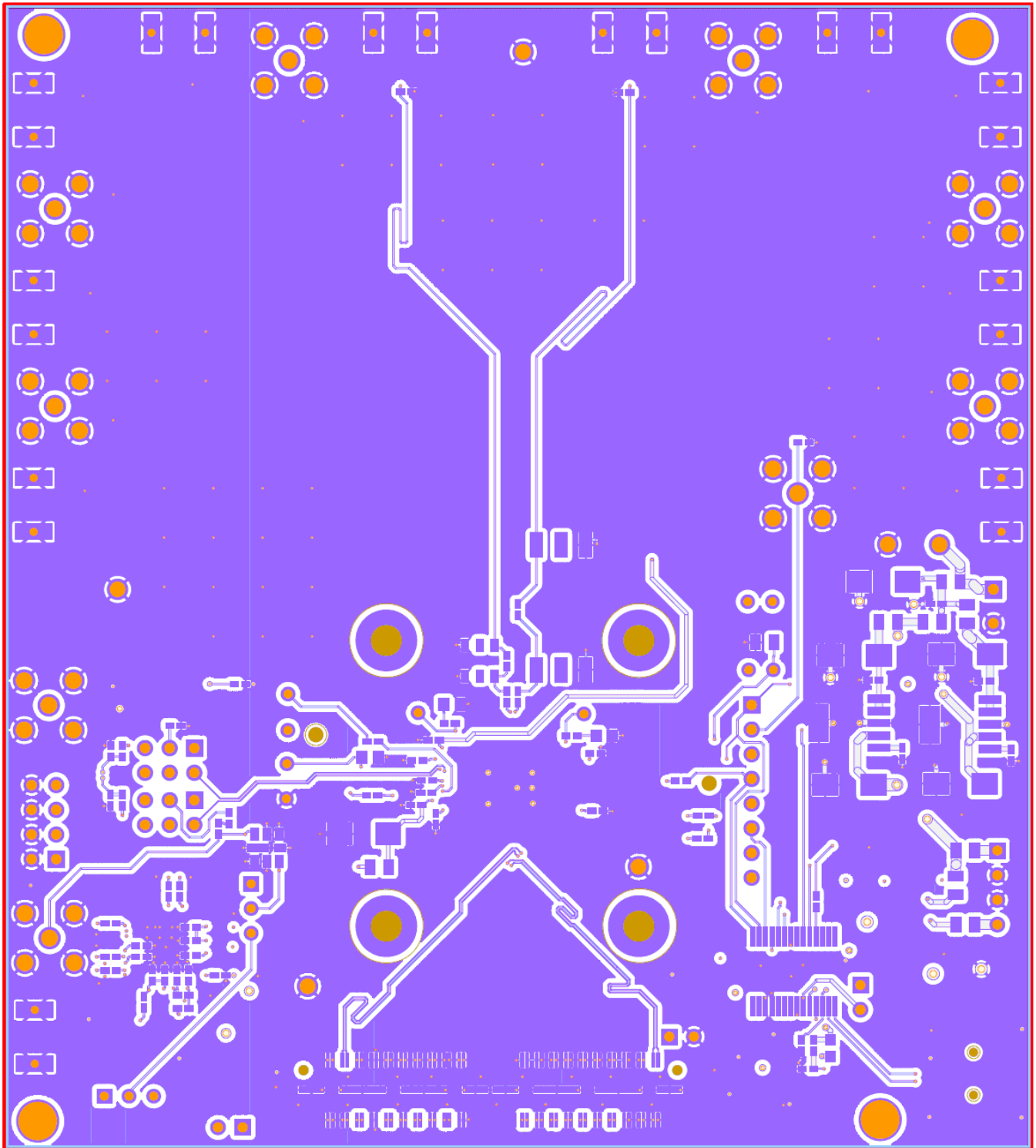


Figure 23. Bottom Layer – Signal

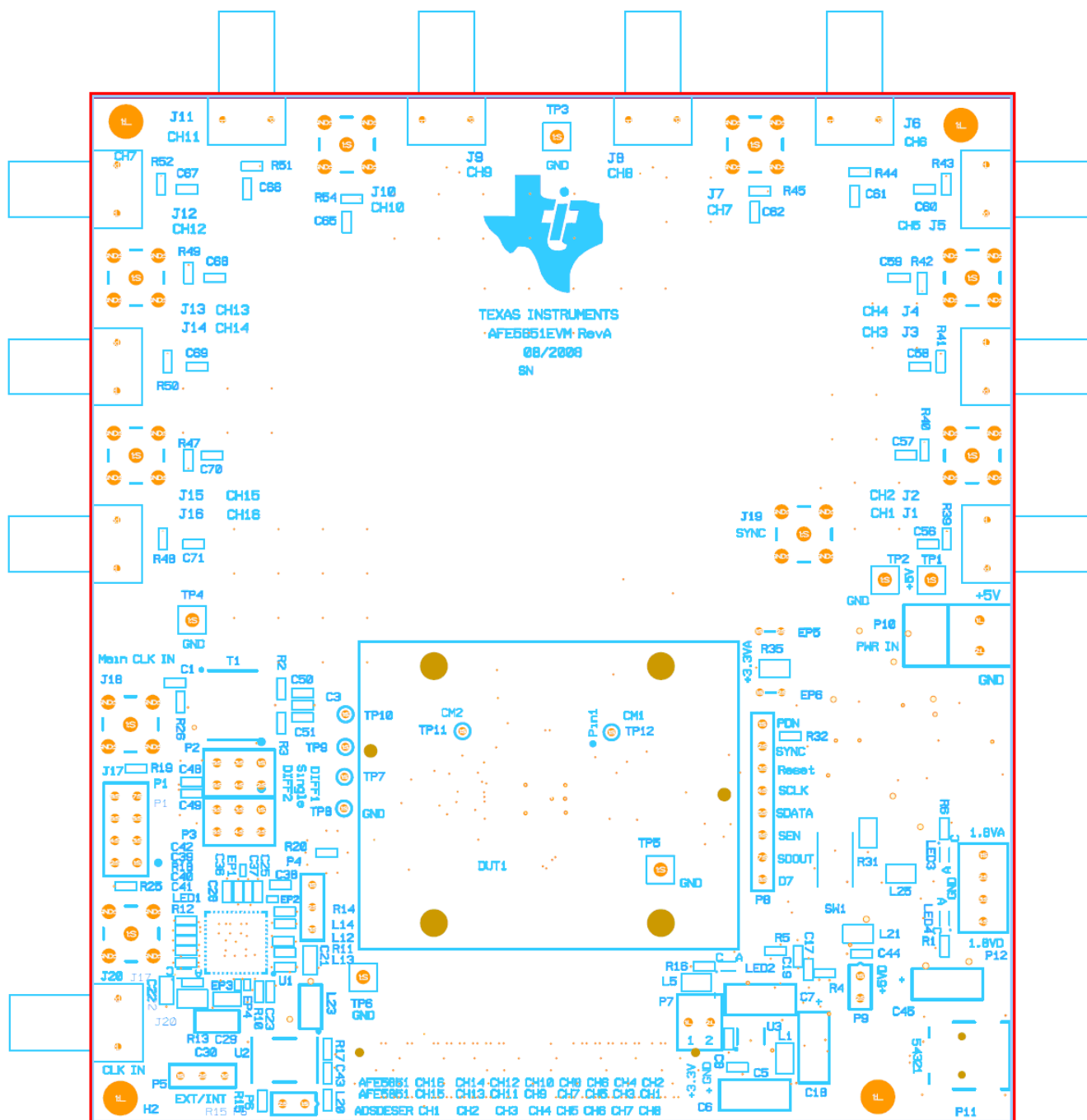


Figure 24. Top Silk Screen Layer

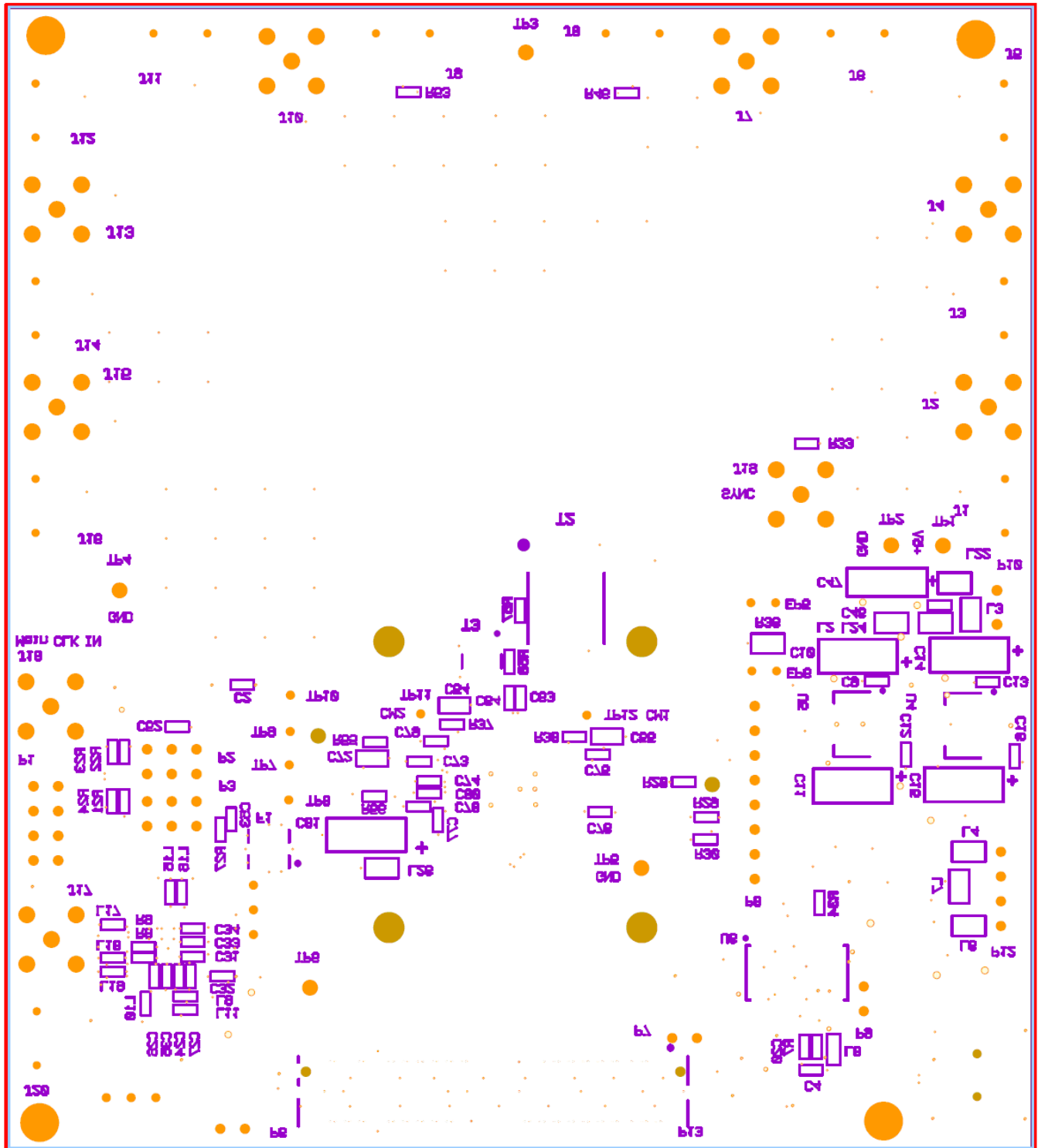


Figure 25. Bottom Silk Screen Layer

4.3 Bill of Materials

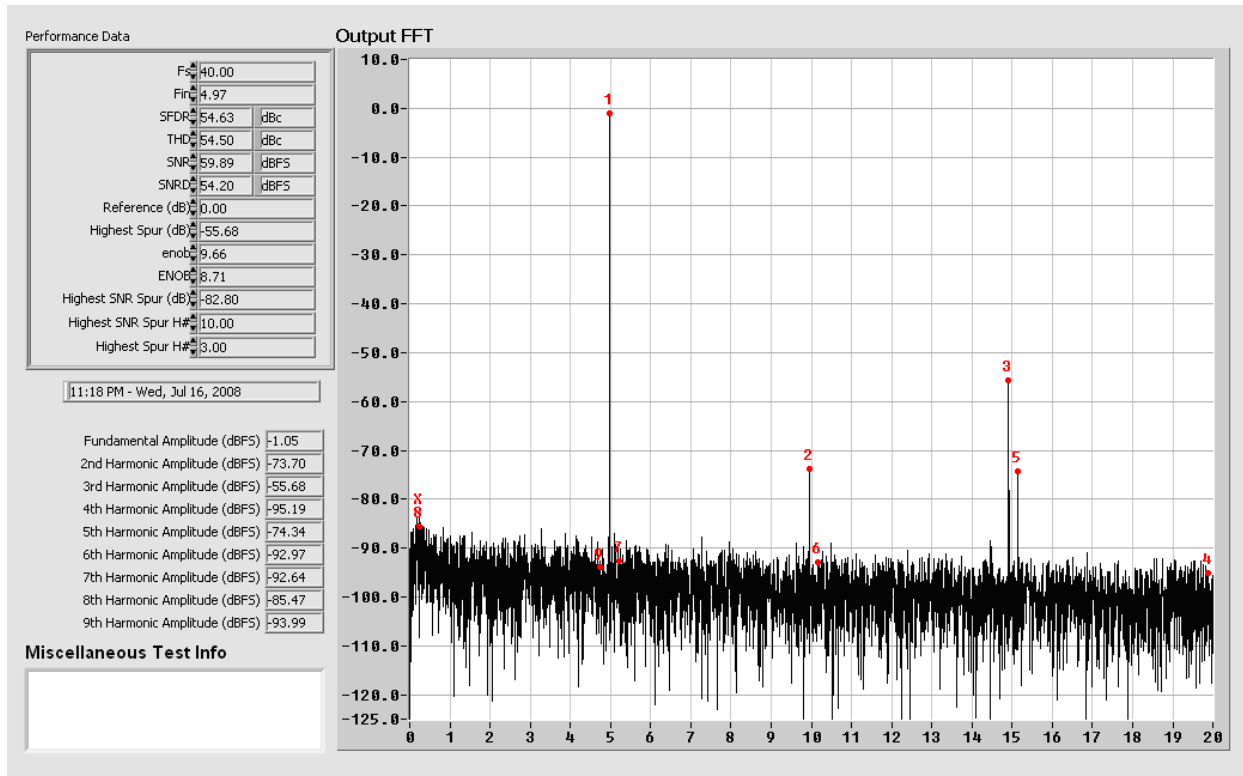
| ITEM | MFG | MFG PART# | REF DES | VALUE or FUNCTION |
|------|-------------------------------|---------------------|--|--|
| 1 | Kemet | C0402C104K8PAC | C1–C5, C8, C9, C12, C13, C16, C17, C19, C20, C24–C28, C31–C44, C46, C48–C53, C56–C80 | Capacitor, SMT, 0402, Ceramic, 0.1µF, 10V, 10%, X5R |
| 2 | Murata | GRM155R60J225ME15D | C23 | Capacitor, SMT, 0402, Ceramic, 2.2µF, 6.3V, 20%, X5R |
| 3 | Panasonic | ECJ-1VB0J475K | C29 | Capacitor, SMT, 0603, Ceramic, 4.7µF, 6.3V, 10%, X5R |
| 4 | Panasonic | ECJ-1VB1A105K | C54, C55, C72 | Capacitor, SMT, 0603, Ceramic, 1.0µF, 10V, 10%, X5R |
| 5 | Taiyo Yuden | JMK107BJ106MA-T | C21, C22 | Capacitor, SMT, 0603, Ceramic, 10µF, 6.3V, 20%, X5R |
| 6 | Murata | GRM31CR60J476ME19B | C30 | Capacitor, SMT, Ceramic, 1206, 47µF, 6.3V, 20%, X5R |
| 7 | AVX | TPSC106K025R0500 | C81 | 10%, 25V, 10uF |
| 8 | AVX | TPSC226K016R0375 | C6, C7, C10, C11, C14, C15, C18, C45, C47 | 10%, 16V, 22µF |
| 9 | Samtec | SMA-J-P-X-ST-EM1 | J1, J3, J5, J6, J8, J9, J11, J12, J14, J16, J20 | SMA Jack, Edge mount, 062PCB, Brass/Gold, Straight, 50 Ω |
| 10 | Samtec | SMA-J-P-H-ST-TH1 | J2, J4, J7, J10, J13, J15, J17–J19 | SMA Coax straight PCB Jack, SMT, 175TL, 50 Ω, Gold |
| 11 | Advanced Connectek | MNE20-5K5P10 | P11 | MINI-AB USB OTG Receptacle R/A SMT Type |
| 12 | Samtec | QTH-040-01-L-D-DP-A | P13 | Connector, SMT, 80P, 0.5mm, FEM, DIFF Pair, Receptacle, 168H |
| 13 | Epson Toyocom | HF-372A | F1(Uninstalled) | (Customer Supply) Crystal filter miniature radio equipment/IF |
| 14 | TI | CDCE62005 | U1(Uninstalled) | Jitter cleaner CDCE62005 |
| 15 | Not Installed | PAD0201(UN) | EP2, EP3 | (Uninstalled Part) Empty pad, SMT, 0201 |
| 16 | Murata | BLM15BD102SN1D | L9–L20 | Ferrite bead, SMT, 0402, 1kΩ, 200 mA |
| 17 | Murata | BLM18EG601SN1D | L8 | Ferrite bead, SMT, 0603, 600 Ω at 100 MHz, 25%, 800 mA |
| 18 | Steward | HI0805R800R-00 | L1–L7, L21, L22, L24–L26 | Ferrite, SMT, 0805, 80 Ω at 100 MHz, 5 A |
| 19 | Steward | LI1206H151R-00 | L23 | Ferrite, SMT, 1206, 150 Ω at 100 MHz, 0.8 A |
| 20 | Molex | 39357-0002 | P10 | Header, THRU, Power, 2P, 3.5MM, Eurostyle |
| 21 | Samtec | SSQ-104-02-F-D | P1 | Header, THU, 8P, 2X4, 100LS, FEM, VERT, 194TL |
| 22 | Samtec | TSW-103-08-G-D | P2, P3 | Header, THU, 6P, 2X3, male, dual row, 100LS, 200TL |
| 23 | Tyco Electronics | 103321-2 | P6, P9 | Header w/shunt, 2P, 100LS |
| 24 | Molex | 22-23-2021-P | P7 | MALE, 2PIN, 0.100CC w/ friction lock |
| 25 | Mill-Max | 350-10-103-00-006 | P4, P5 | Header, THU, MAL, 0.1LS, 3P, 1X3, 284H, 110TL |
| 26 | Molex | 22-23-2041 | P12 | 4P, VERT, Friction lock |
| 27 | Samtec | TSW-108-05-G-S | P8 | Header, THU, 8P, 1X8, male, single row, 100LS, 130TL |
| 28 | TI | TPS79618DCQR | U5 | Ultralow-noise HI PSRR Fast RF 1-A LDO Linear regulator, 1.8V |
| 29 | TI | TPS79633DCQR | U4 | Ultralow-noise HI PSRR Fast RF 1-A LDO Linear regulator, 3.3V |
| 30 | TI | TPS79318DBV | U3 (UNINSTALLED) | 1.8V, Ultralow-noise HI PSRR Fast RF 200 mA LDO Linear regulator |
| 31 | Future Technology Device Int. | FT245RL | U6 | USB FIFO IC Incorporate FTDICHIP-ID Security dongle |
| 32 | Tyco Electronics | 103321-2 | EP5, EP6 | Header W, 2P, 100LS |
| 33 | Panasonic | LNJ308G8PRA | LED1, LED4 | LED, SMT, 0603, pure green, 2.03V |

| ITEM | MFG | MFG PART# | REF DES | VALUE or FUNCTION |
|------|----------------------|-------------------------|--|--|
| 34 | Panasonic | LNJ808R8ERA | LED2, LED3 | LED, SMT, 0603, orange, 1.8V |
| 35 | ECS | ECS-3953M-400-BN | U2 | OSC, SMT, 3.3V, 50ppm, -40~85C, 5nS, 40.000 MHz |
| 36 | Vishay | CRCW0402000Z | R37, R38, R55, R56 | 0 Ω Jumper, SMT, 0402, thick film, 0 Ω , 1/16W, 5% |
| 37 | Vishay | CRCW04021002F100 | R28, R29, R30 | Resistor, SMT, 0402, 10K, 1/16W, 1%, 100ppm |
| 38 | Panasonic | ERJ-2GE0R00X | R8, R10–R12, R15, R19, R20, R32, R34, R57, R58 | Resistor/jumper, SMT, 0402, 0 Ω , 5%, 1/16W |
| 39 | Panasonic | ERJ-2GEJ0000(UN) | R5, R7, R9, R14, R17, R18 | (UNINSTALLED PART) |
| 40 | Panasonic | ERJ-2GEJ131 | R21, R22 | Resistor, SMT, 0402, thick film, 5%, 1/16W, 130 |
| 41 | Panasonic | ERJ-2GEJ49R9(UN) | R25, R26 | (UNINSTALLED PART) |
| 42 | Panasonic | ERJ-2GEJ820 | R23, R24 | Resistor, SMT, 0402, thick film, 5%, 1/16W, 82 |
| 43 | Panasonic | ERJ-2RKF1000X | R2, R3 | Resistor, SMT, 0402, 100 Ω , 1%, 1/16W |
| 44 | Panasonic | ERJ-2RKF1001X | R4 | Resistor, SMT, 0402, 1.00K, 1%, 1/16W |
| 45 | Panasonic | ERJ-2RKF3320X | R1, R6, R16 | Resistor, SMT, 0402, 332 Ω , 1%, 1/16W |
| 46 | Panasonic | ERJ-2RKF49R9X | R27, R39, R40–R54 | Resistor, SMT, 0805 49.9 Ω , 1%, 1/16W |
| 47 | Vishay | CRCW08051002F | R31, R35, R36 | Resistor, SMT, 0805, thick film, 1%, 1/8W, 10.0K |
| 48 | Panasonic | ERJ-6RQF5R1V | R13 | Resistor, SMT, 0805, 1%, 1/8W, 5.1 Ω |
| 49 | Panasonic | ERJ-1GE0R00C | EP1, EP4 | Resistor, SMT, 0201, thick film, 0 Ω , 5%, 0 Ω Jumper, 1/20W |
| 50 | NONE | RES-SMT0402_UNINSTALLED | R33 | RES 0402 UNINSTALLED |
| 51 | TI | AFE5851 | DUT1 | AFE5851 16-channel ultrasound analog front-end |
| 52 | ITT Industries | PTS635SK25SM | SW1 | Switch, SMT, 2P, SPST-NO, 2.5mm Height, MOM, rectangular, 0.05A, 12V |
| 53 | Keystone Electronics | 5005 | TP1 | Testpoint, THU, compact, 0.125LS, 130TL, red |
| 54 | Keystone Electronics | 5006 | TP2–TP6 | Testpoint, THU, compact, 0.125LS, 130TL, black |
| 55 | Mini-Circuits | ADTT1-6T | T1 | RF Transformer wideband, 0.03–125 MHz |
| 56 | Coilcraft | WB36-1SLB | T2 (NOT INSTALLED) | Transformer, SMT, 6P, wideband, 36:1, 0.100–45MHz |
| 57 | Coilcraft | WBC4-1TLB | T3 (NOT INSTALLED) | Transformer, SMT, 6P, 1:4, 0.250–750MHz |
| 58 | PEM | KFS2-M2.5 | DUT1 | Install first (Manually calculate the QTY) |
| 59 | AMP | 531220-2 | P6, P9 | |

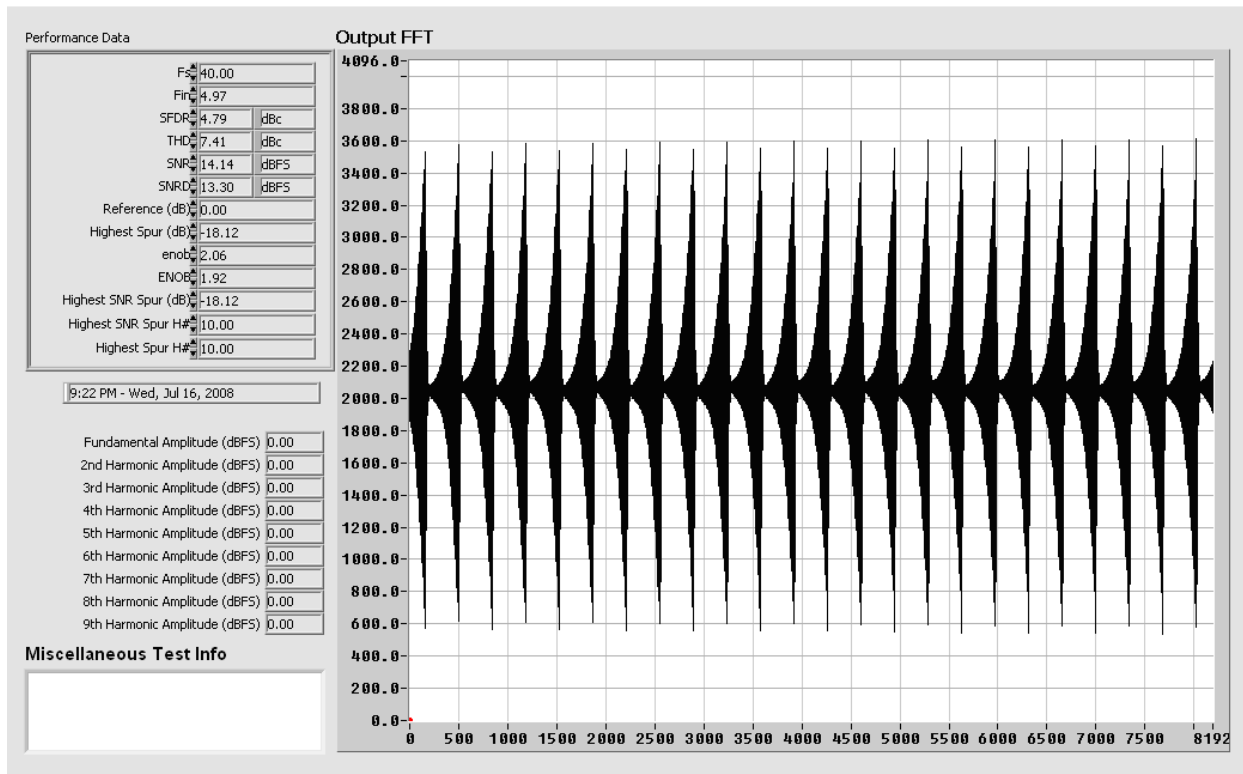
5 Typical Performance

This chapter provides some typical performance of the AFE5851EVM to assist users to verify their setup.

A typical performance plot of the AFE5851 is shown in [Figure 26](#) with 30dB digital gain setting in the 8-CH mode.



(a)



(b)

Figure 26. Typical Performance of AFE5851 — (a) Fixed Gain Mode; (b) Variable Gain Mode

TSW1400 for Evaluating AFE5851

A.1 Introduction

This application note goes through the steps of evaluating the AFE5851 using the TSW1400EVM.

Step 1: Hardware Setup

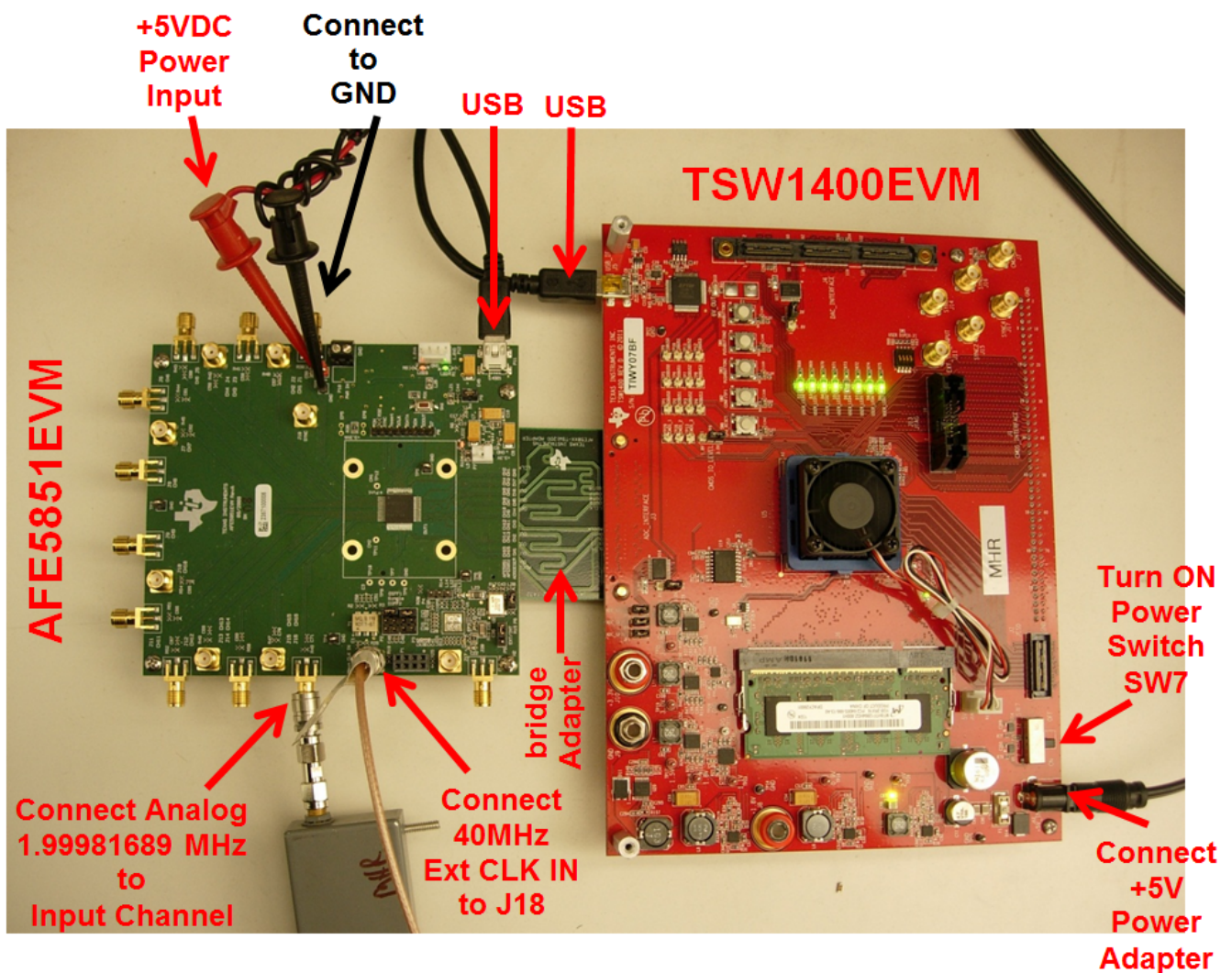


Figure 27. Connection Between TSW1400EVM and AFE5851

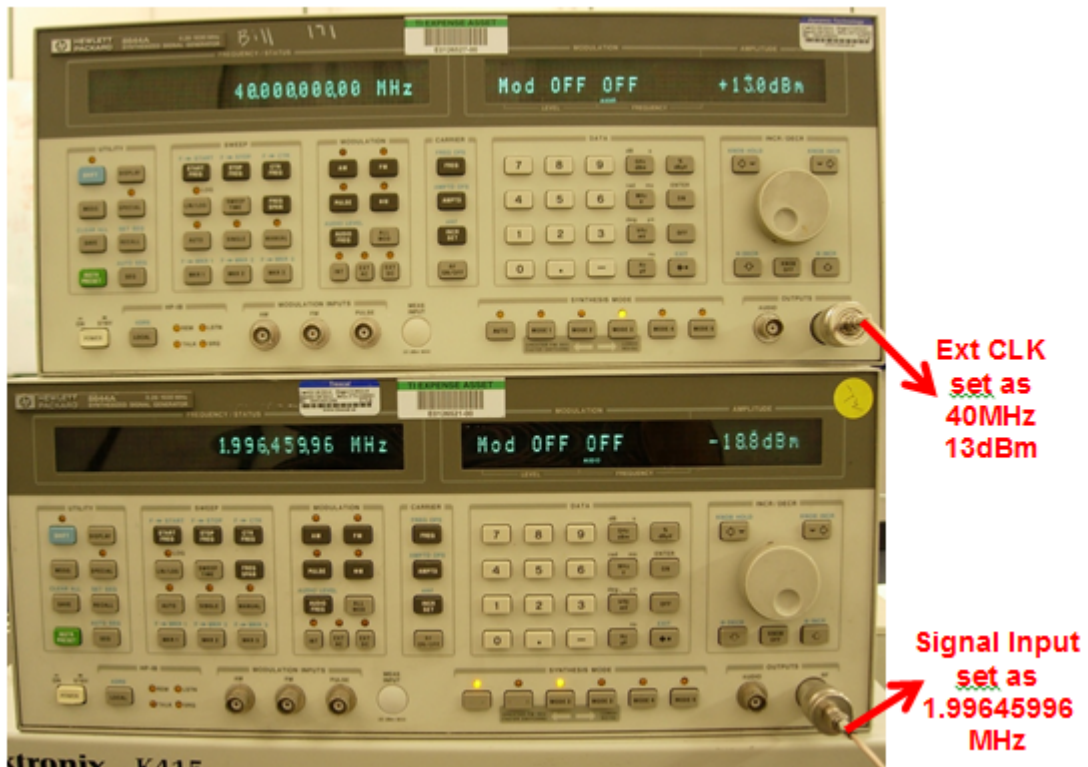


Figure 28. Connecting the Instruments

Step 2: Launch AFE5851 GUI

From PC click Start Menu → All Programs → Texas Instruments → AFE58X1EVM USB SPI → AFE58X1EVM USB SPI

The GUI may be running if the following screen appears.

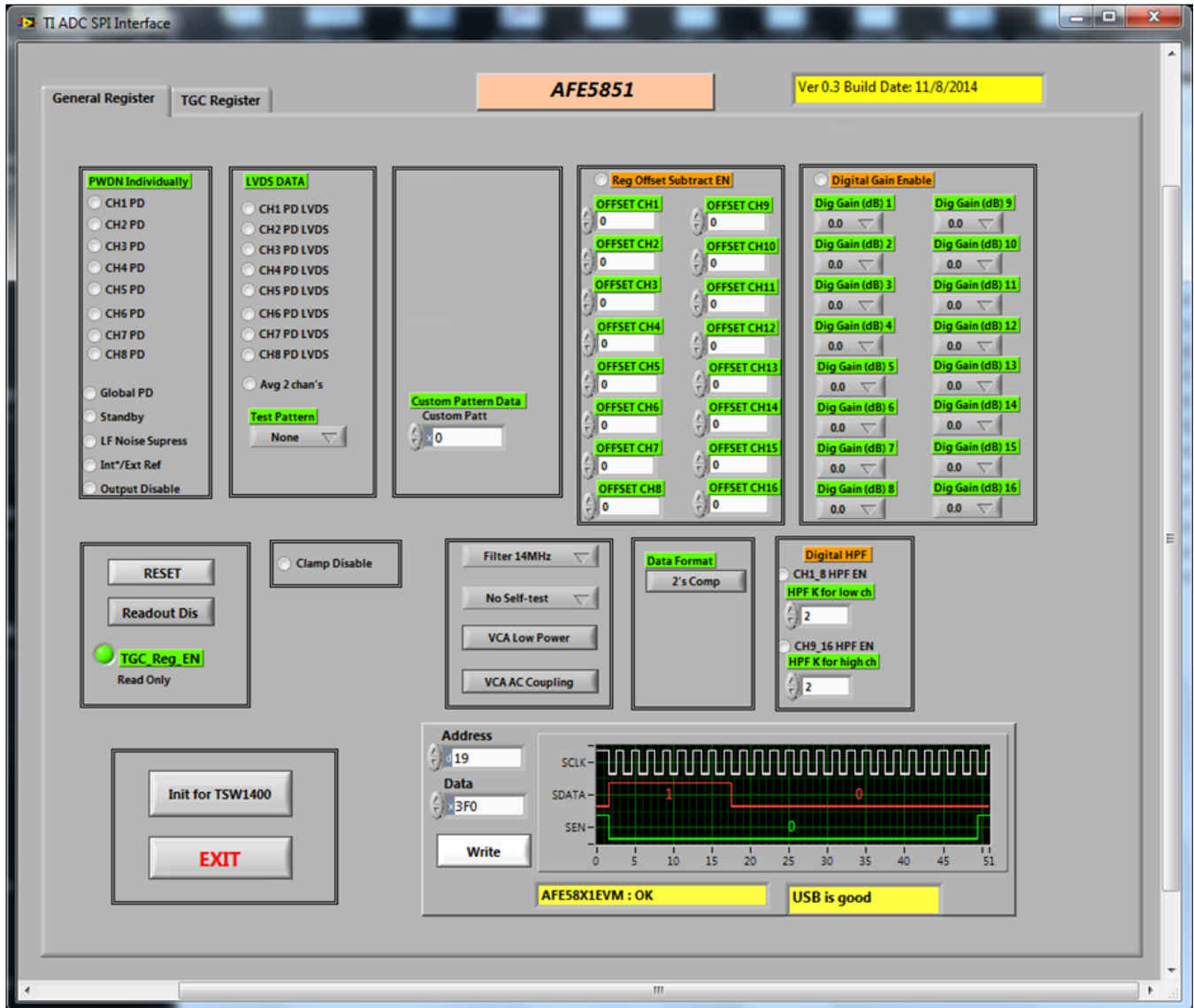


Figure 29. AFE5851 EVM GUI –Run Mode

NOTE: In case the GUI is not running, press the START button of the GUI to run it.

COMMANDS to the AFE5851 GUI:

- Click "Init for TSW1400" to set proper condition to work with TSW1400EVM

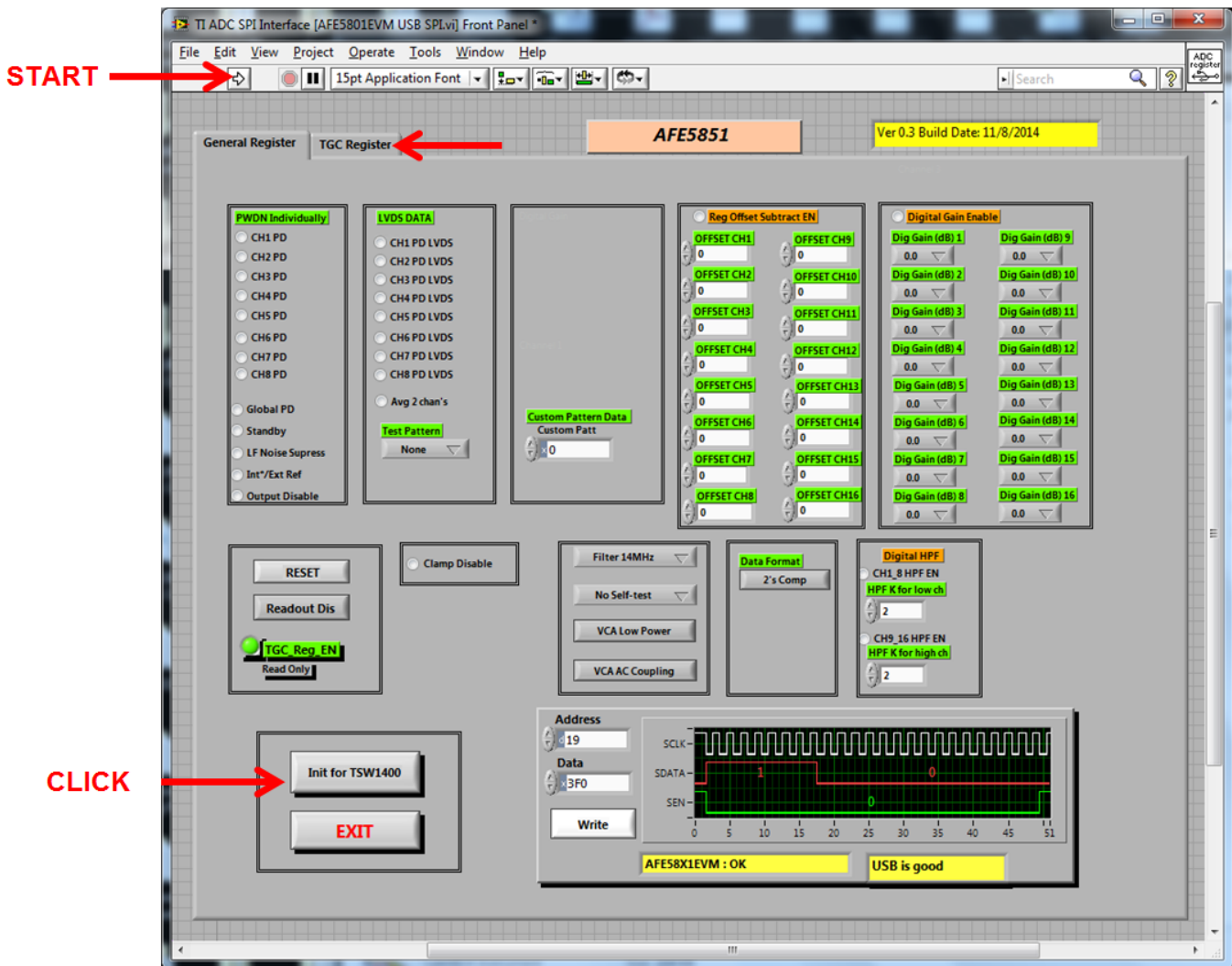


Figure 30. AFE5851 EVM GUI – START Button

- Go to "TGC Register" Tab.
- Press "Variable" toggle button to change the mode to Fixed

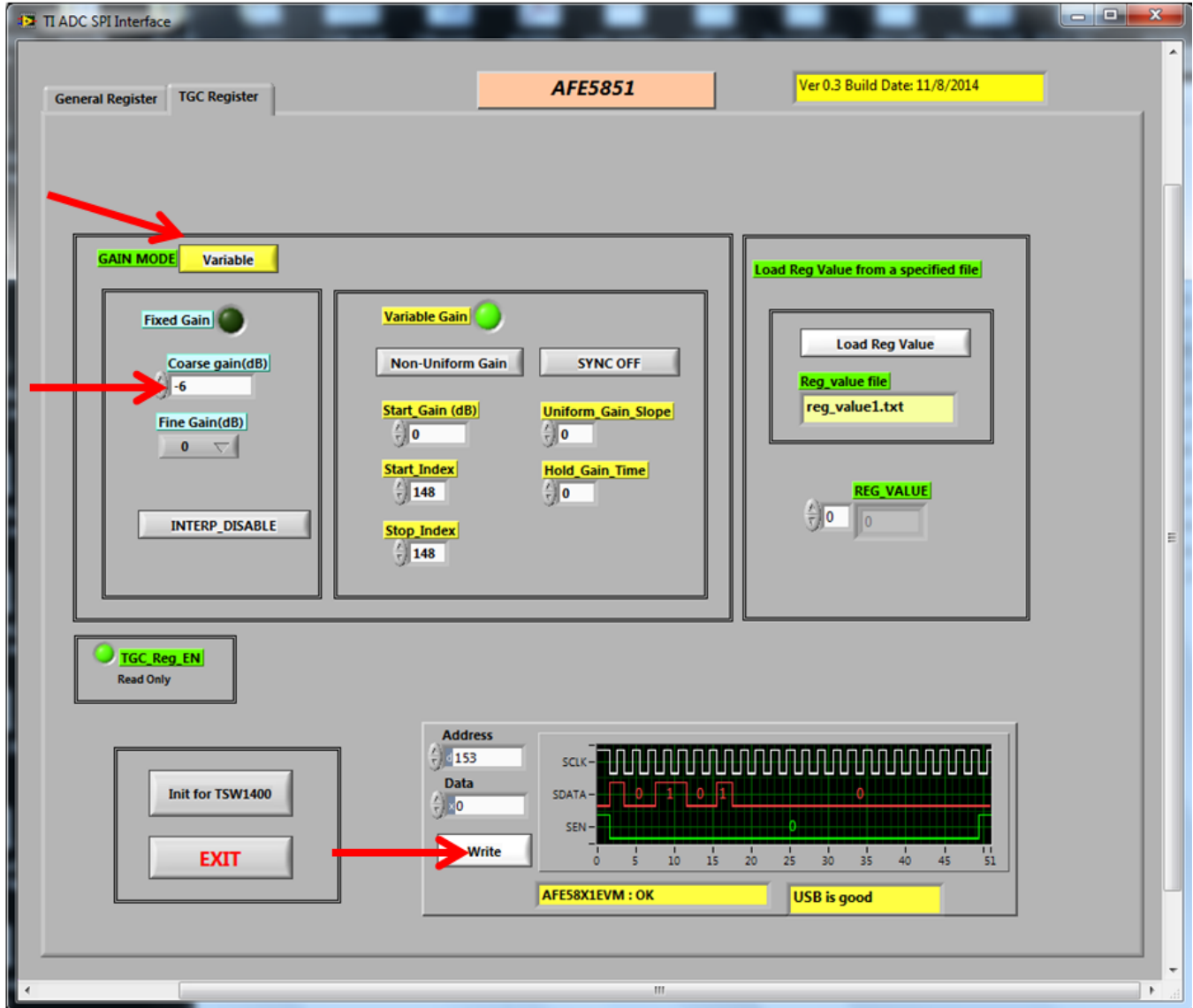


Figure 31. AFE5851 EVM GUI – Variable Gain

- Type 30 and press "Write" button

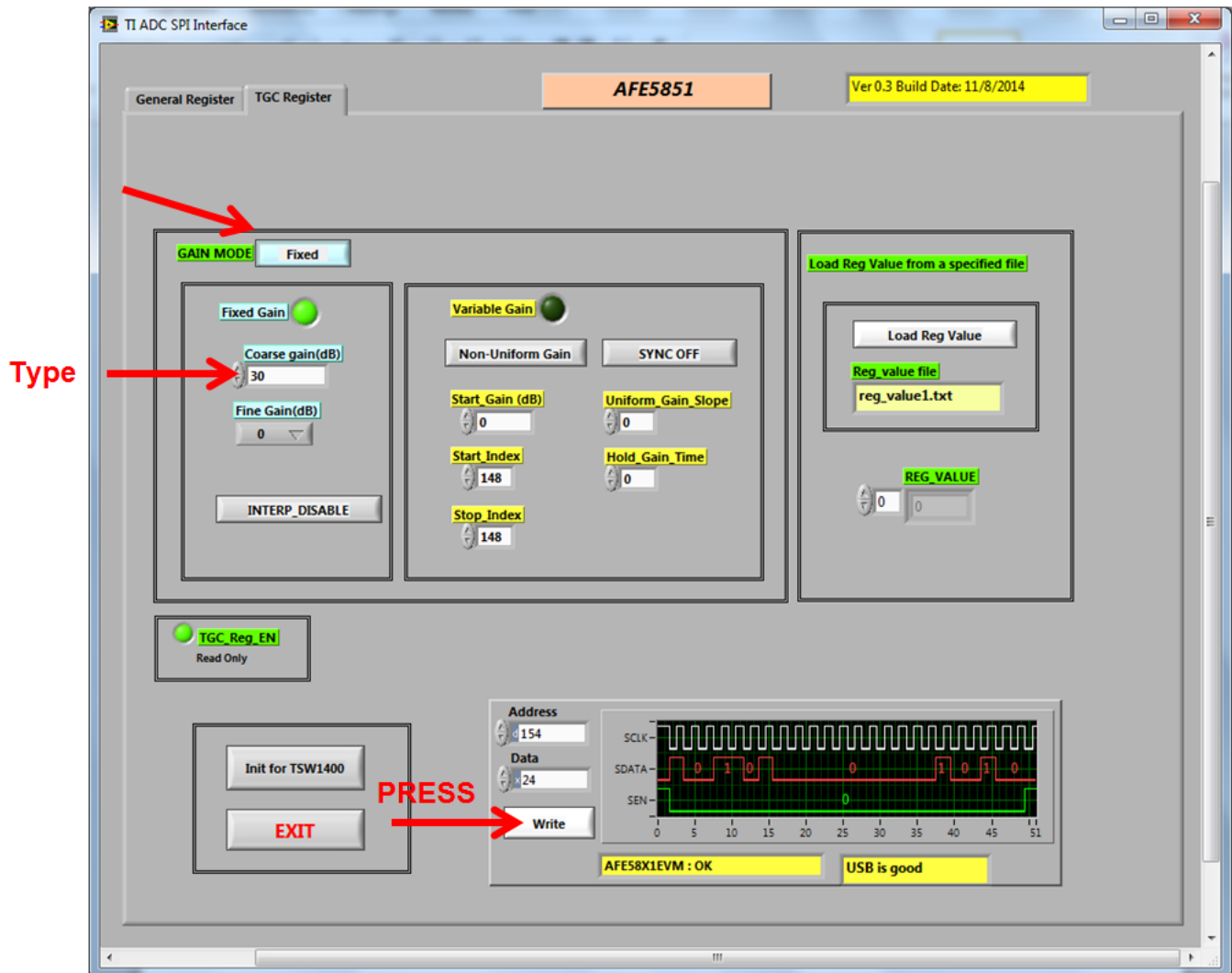


Figure 32. AFE5851 EVM GUI – Setting Fixed Gain

- At this stage the AFE5851 is ready.

Step 3: Launch TSW1400 GUI

Graphics User Interface (GUI)

The TSW1400 provides a GUI for users to evaluate the performance of the device. When GUI is started, [Figure 33](#) appears. Note the areas of interest within the GUI screen:

1. Toolbar
2. Message Window
3. Device Specific Selections
4. Test Parameters
5. Central Pane and result data

Items 1, 3, and 4 are used to set up the test condition.

Items 2 and 5 are test results and status.

For details, refer to TSW1400 User's Guide on the AFE5851 product folder.

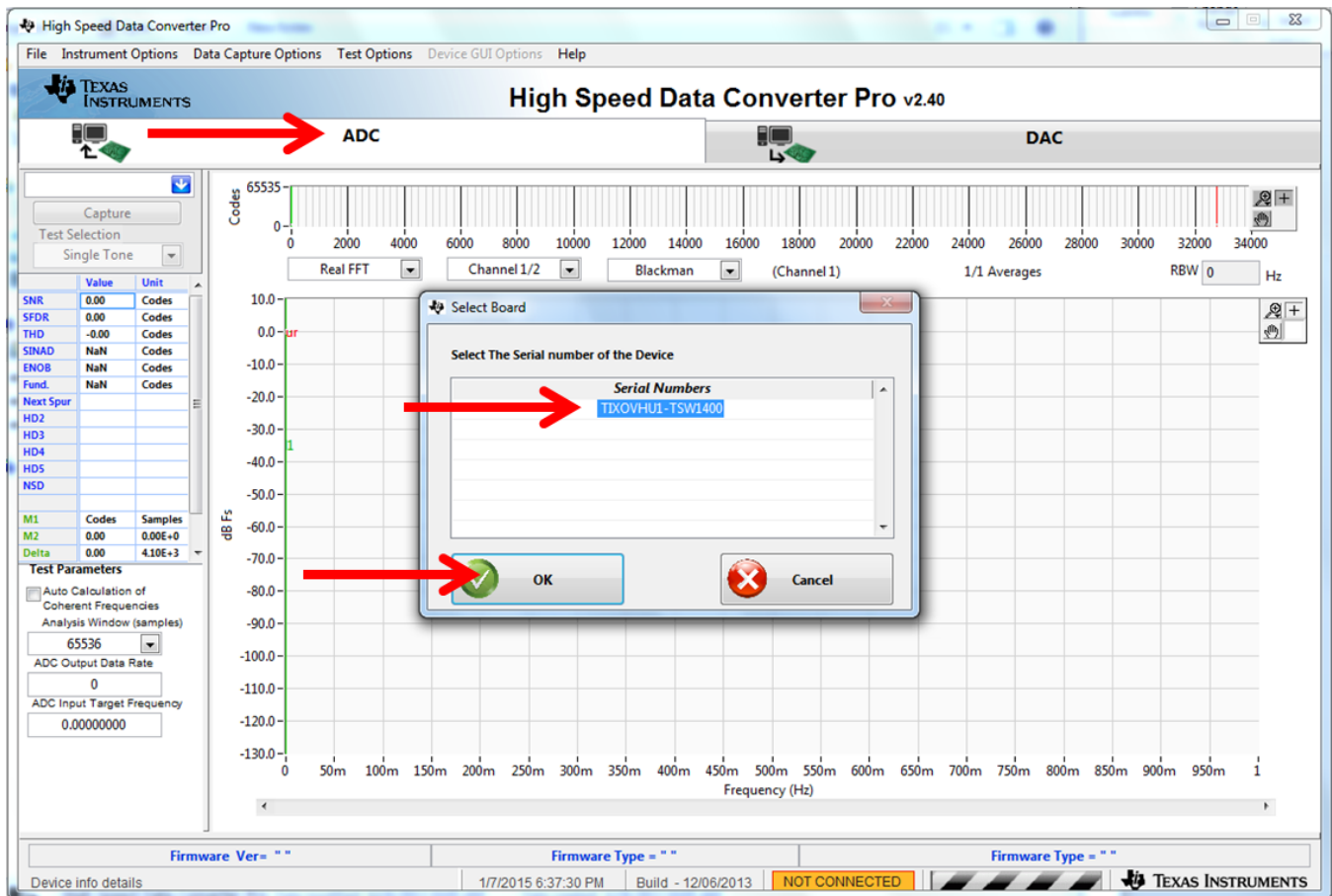


Figure 33. User Interface: Initial Setup Screen

Test Condition

Perform the steps shown on the following figure to set the test conditions.

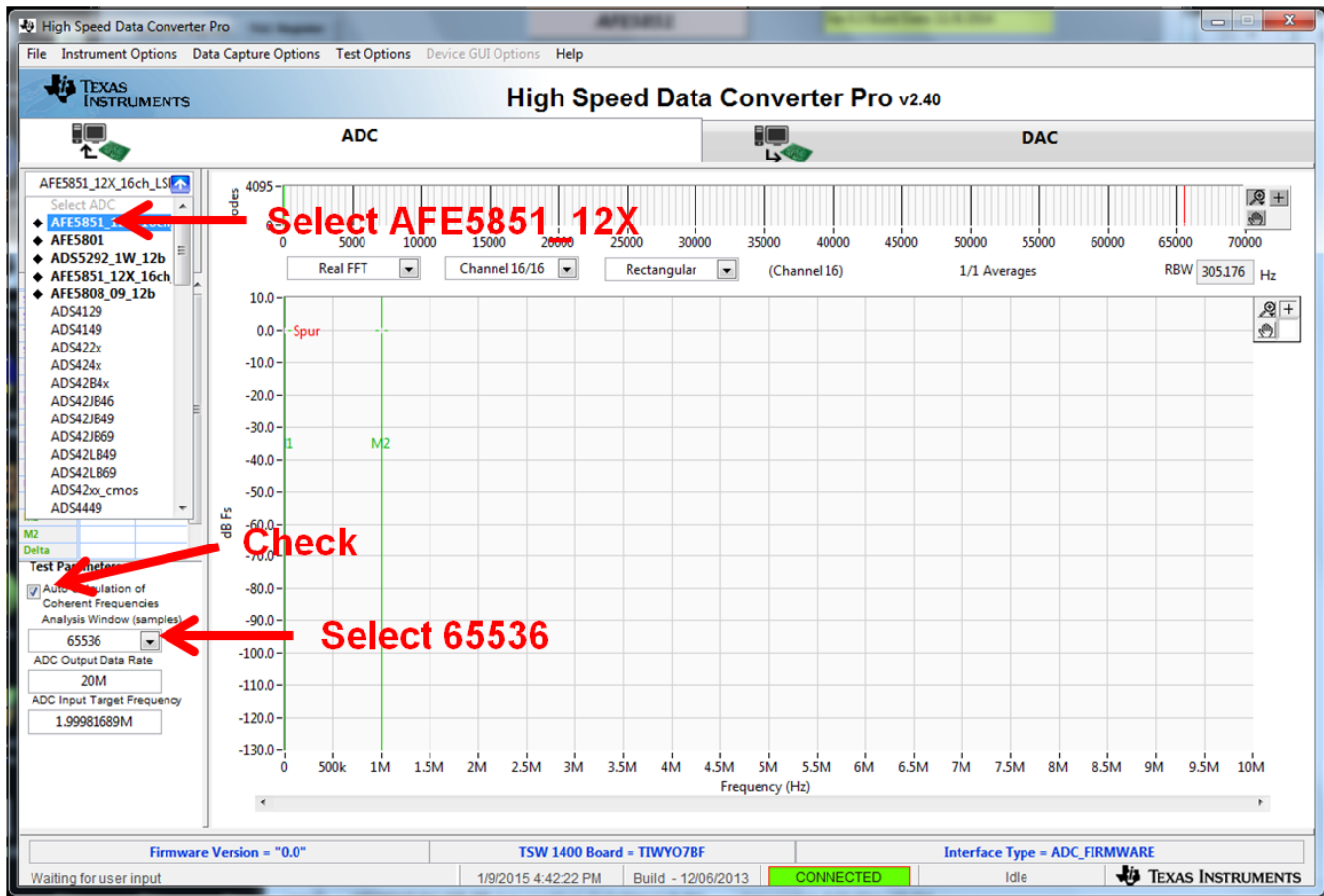


Figure 34. User Interface: Step-by-Step Setup

After completing the steps above, the following figure appears.

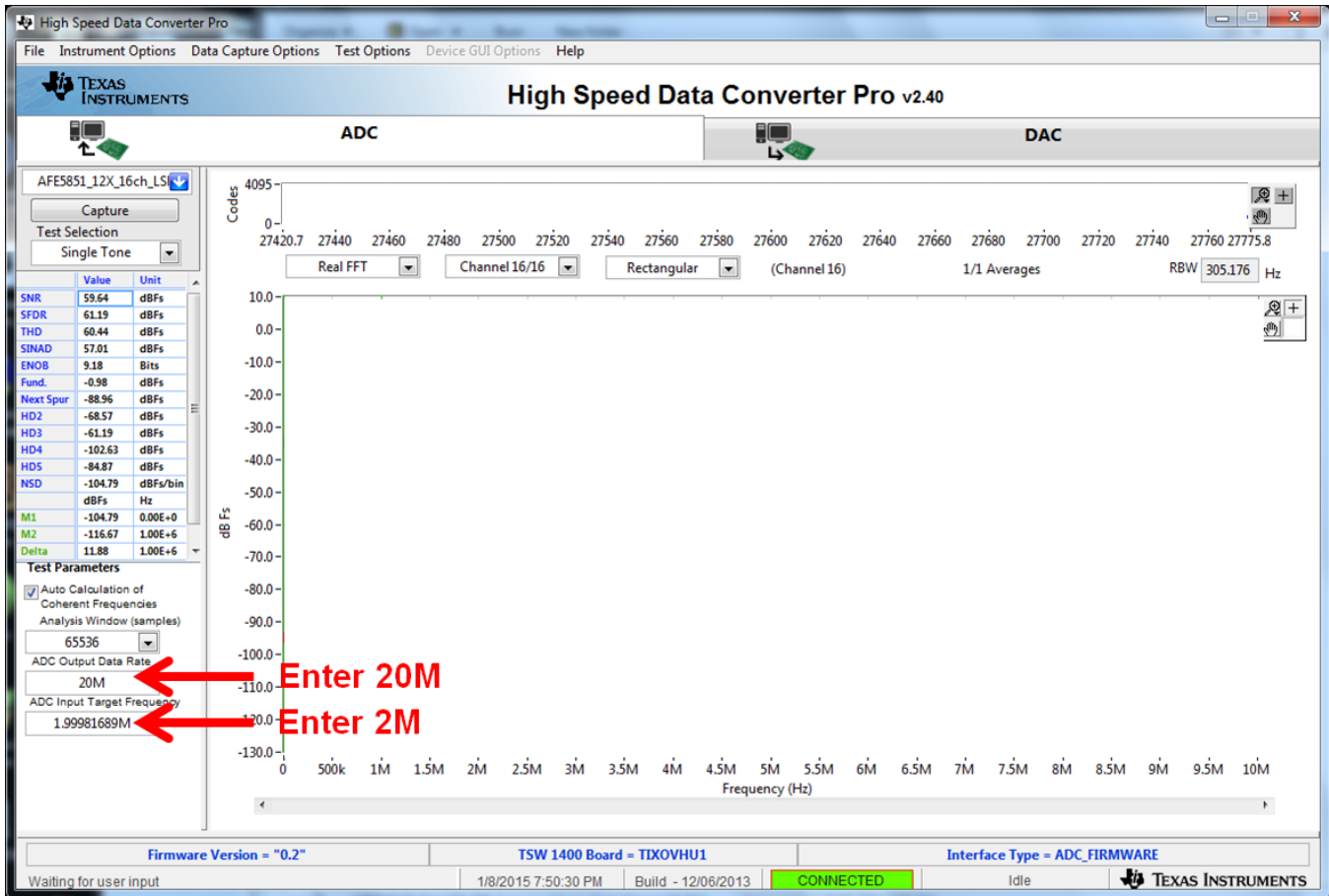


Figure 35. User Interface: Frequency Load Value to Signal Generator

1. Note the "ADC Input Frequency (F_c)" and set the frequency of the signal generator to this frequency.
2. Set Amplitude of the signal generator to -18 to -20 dBm (Input amplitude should be between -1 dBFS to -3 dBFS)
3. Set the Frequency of the Clock Generator to 40 MHz.
4. Set the Amplitude of the Clock Generator to 13 dBm
5. Adjust the GUI:
 - Set ADC Sampling Frequency to 20 MHz. The ADC Input Frequency will be recalculated to a new number by the GUI; use this number (but leave the frequency from the generator set at the previous value).

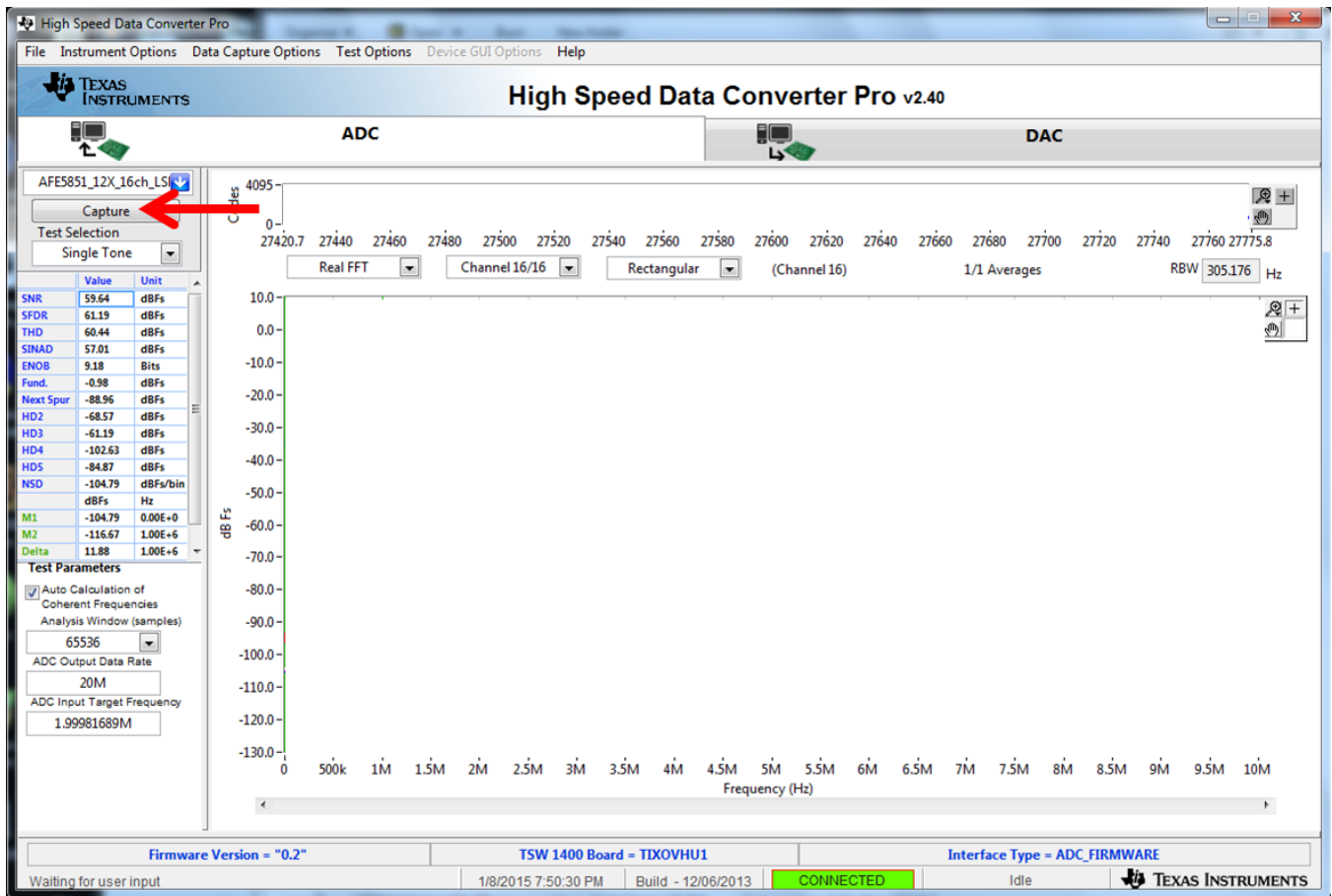


Figure 36. User Interface: Final Setup Screen

Now the user can select the test channel, select the test type by choosing the Single Tone Tab or Time Domain Tab, and start the test.

Single Tone FFT

The Single Tone FFT test is shown in Figure 37. The larger central pane displays the FFT power spectrum, whereas the calculated statistics are grouped into categories on the right of the screen. Settings and inputs relevant to the test are entered in drop-down menus or text input boxes on the left portion of the window.

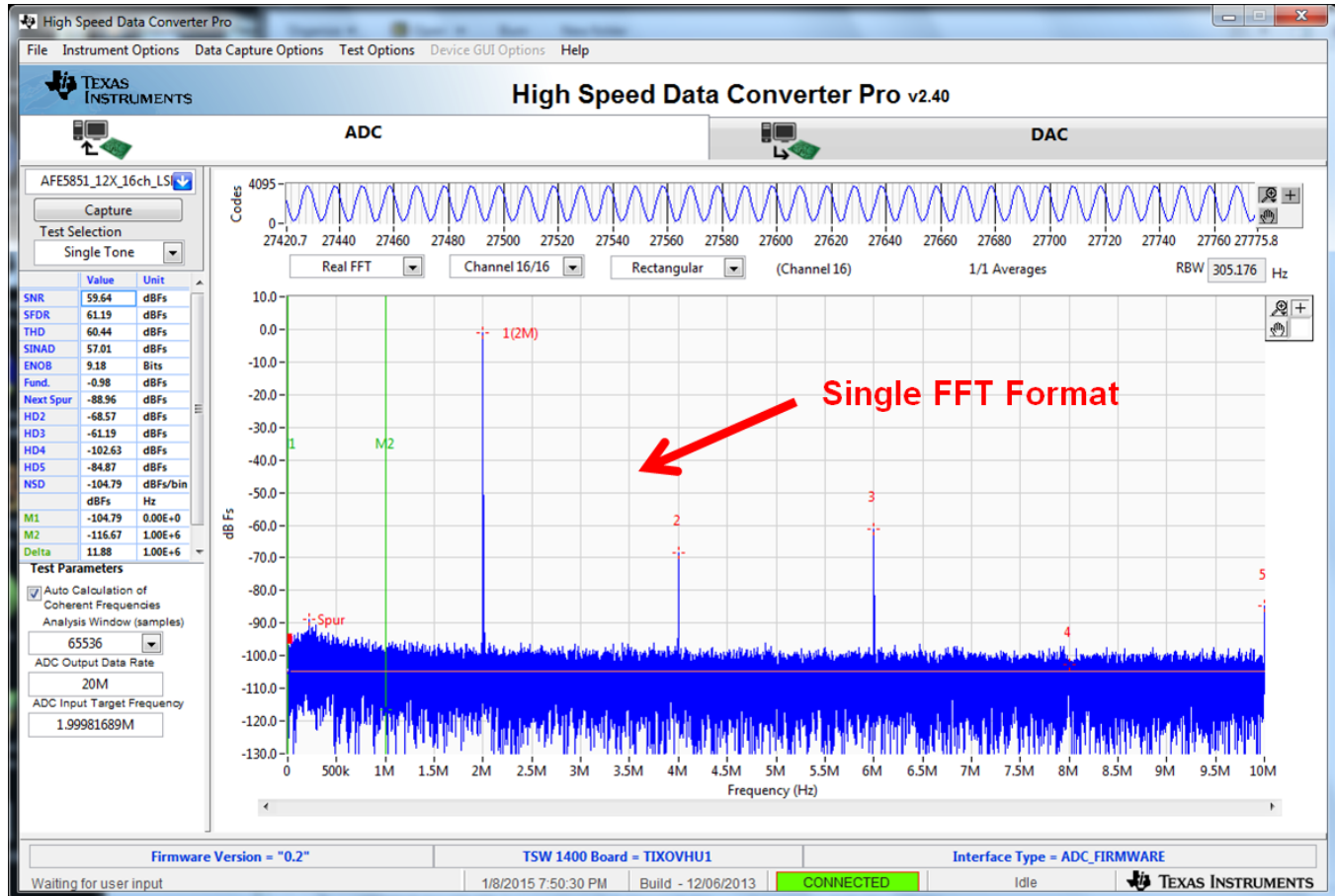


Figure 37. User Interface: Single FFT Format

Time Domain

The Time Domain test is shown in Figure 38. The larger central pane displays the raw sampled data whereas the calculated statistics are grouped into categories on the right of the screen. Settings and inputs relevant to the test are entered in drop-down menus or text input boxes on the left portion of the window.

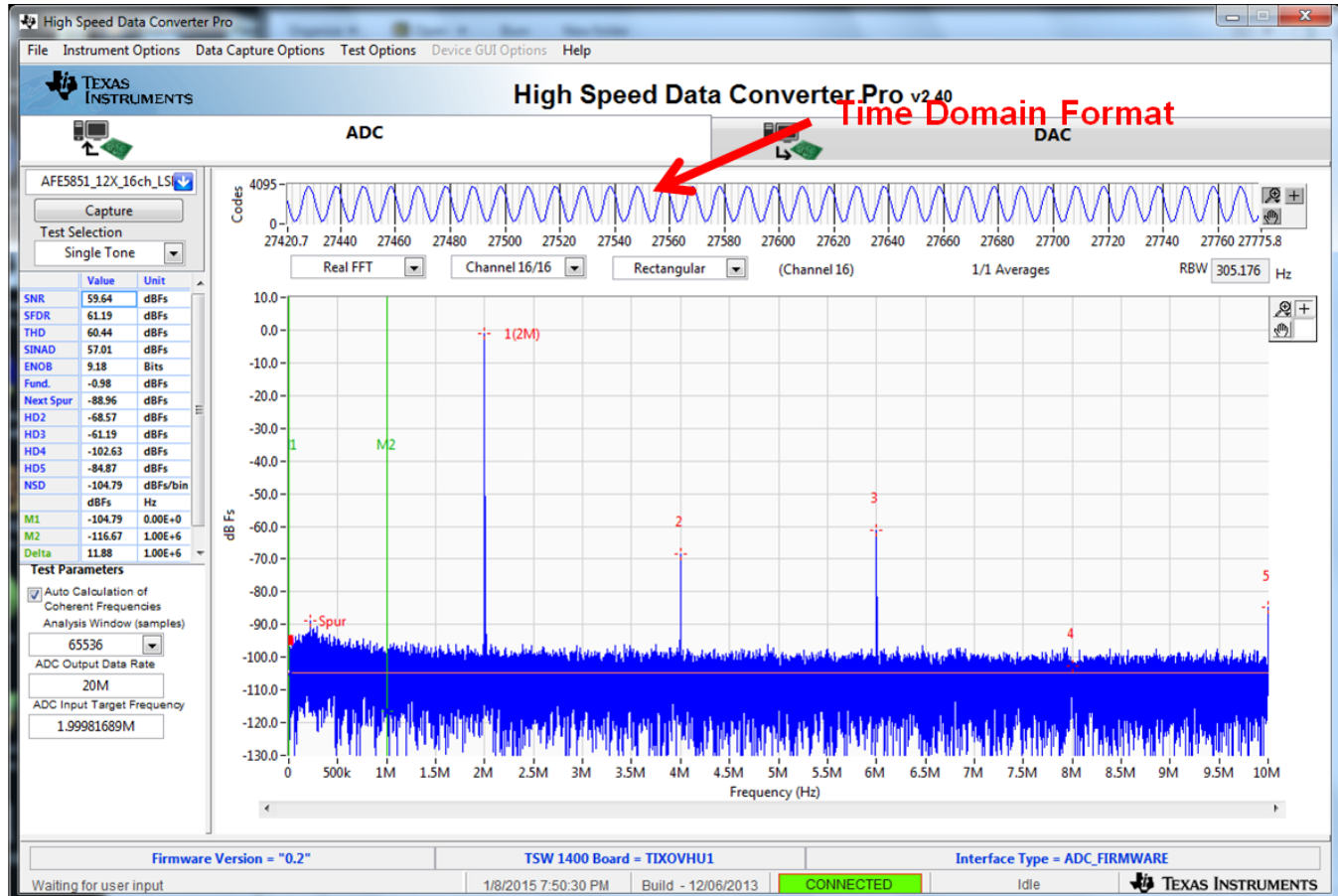


Figure 38. User Interface: Time Domain Format

EXCEL

The raw test sampled data can be saved to a file and processed by EXCEL or some other software.

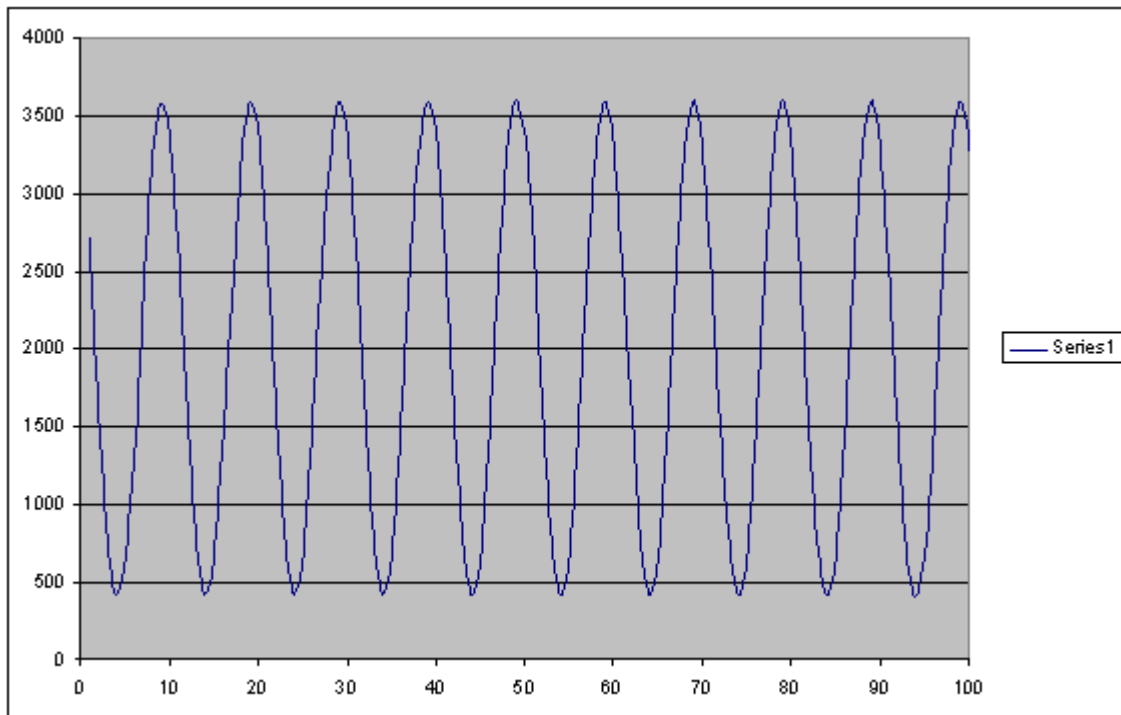


Figure 39. Plot of Saved Sample Data

High Speed Data Converter Pro (HSDCPro) GUI Installation

Download the HSDCPro GUI Installer using this link: [HSDCPro GUI](#)

- Unzip the saved folder and run the installer executable to obtain the pop-up shown in [Figure 40](#).
- Click the *Install* button.

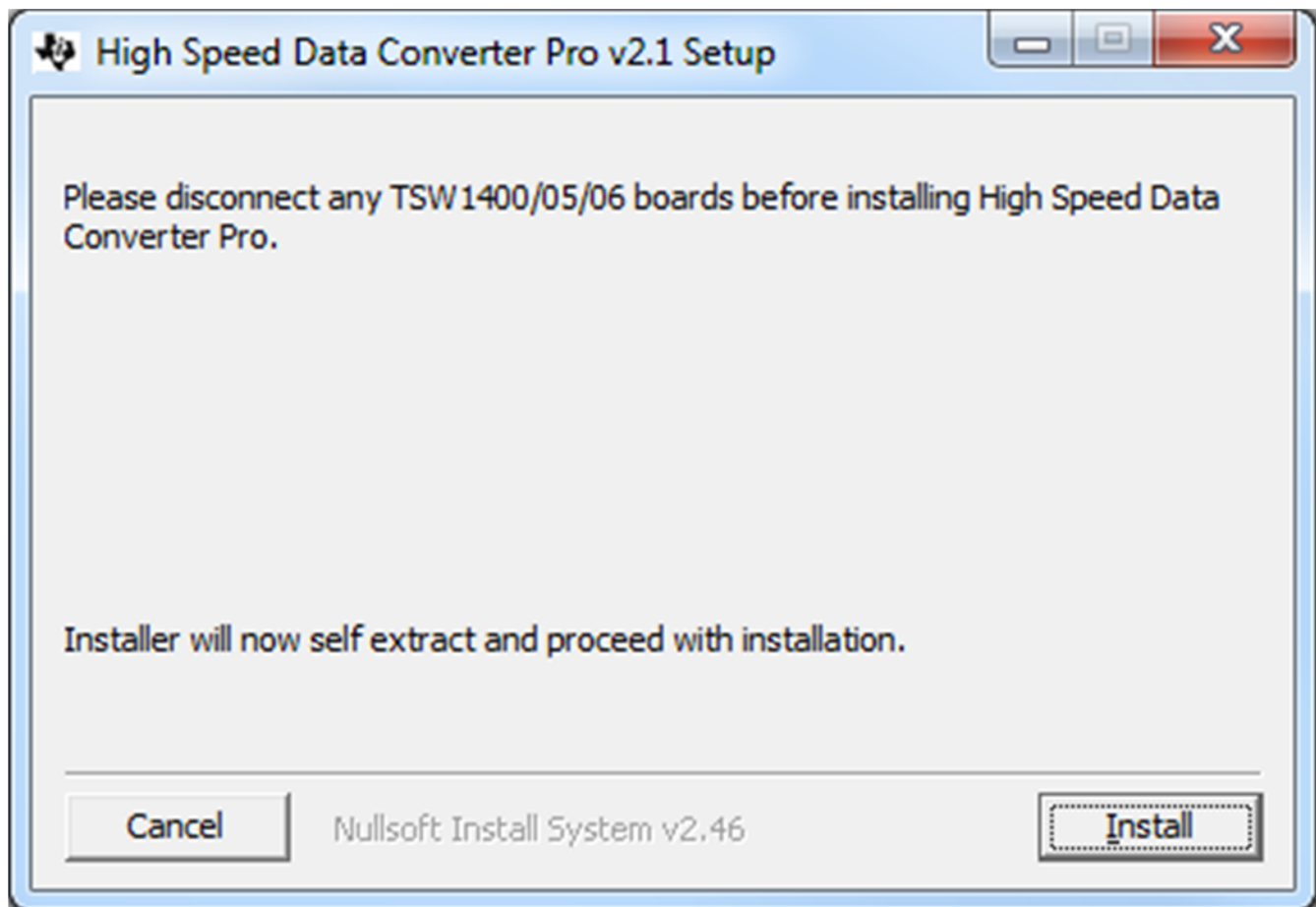


Figure 40. HSDCPro Install (Begin)

- Leave the destination directories as the default location, for the TSW1400GUI installation and press the NEXT button as shown in [Figure 41](#).

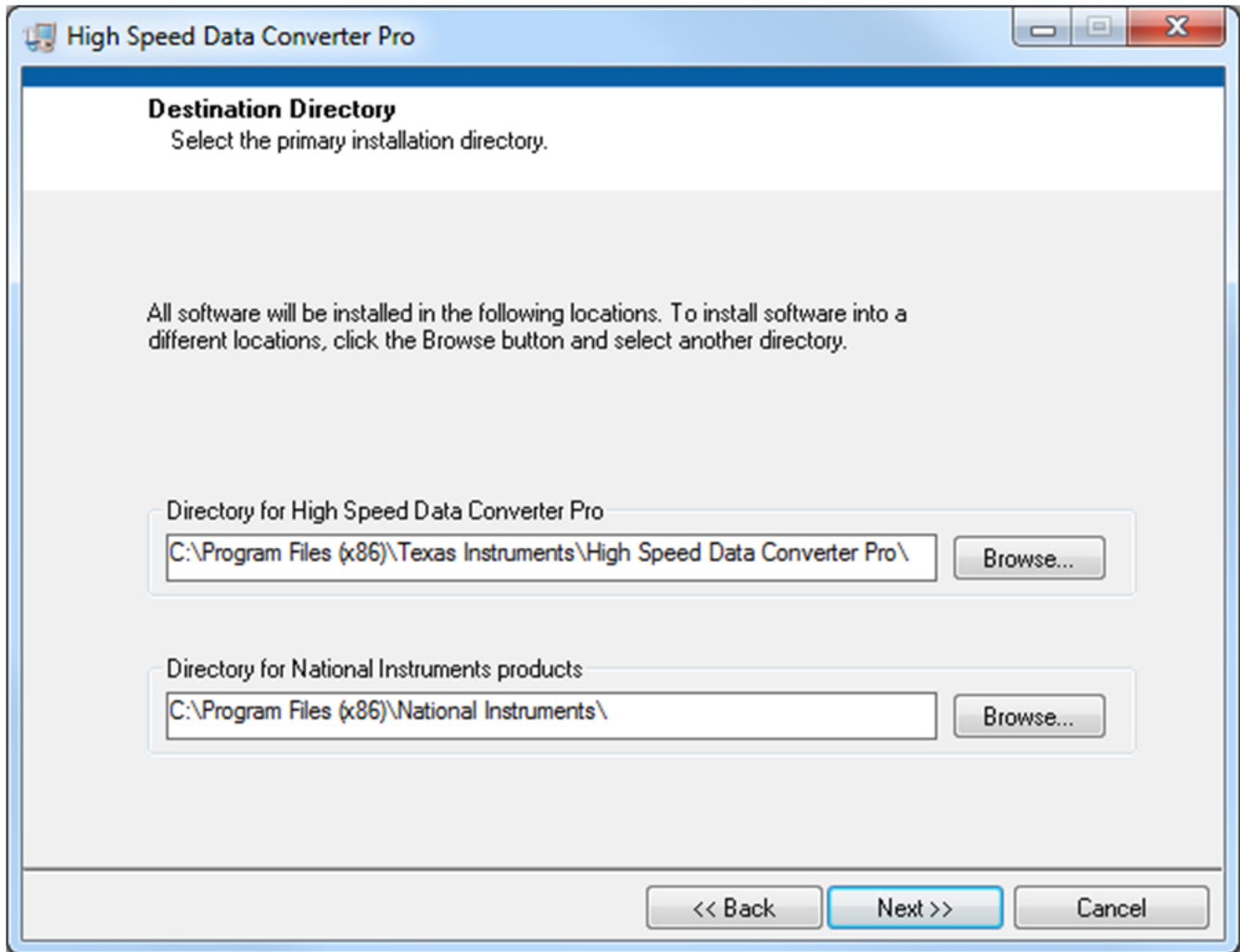


Figure 41. HSDCPro Install (Install Directory)

- Read the License Agreement from Texas Instruments and select *I accept the License Agreement* and press the *Next* button as shown in [Figure 42](#).

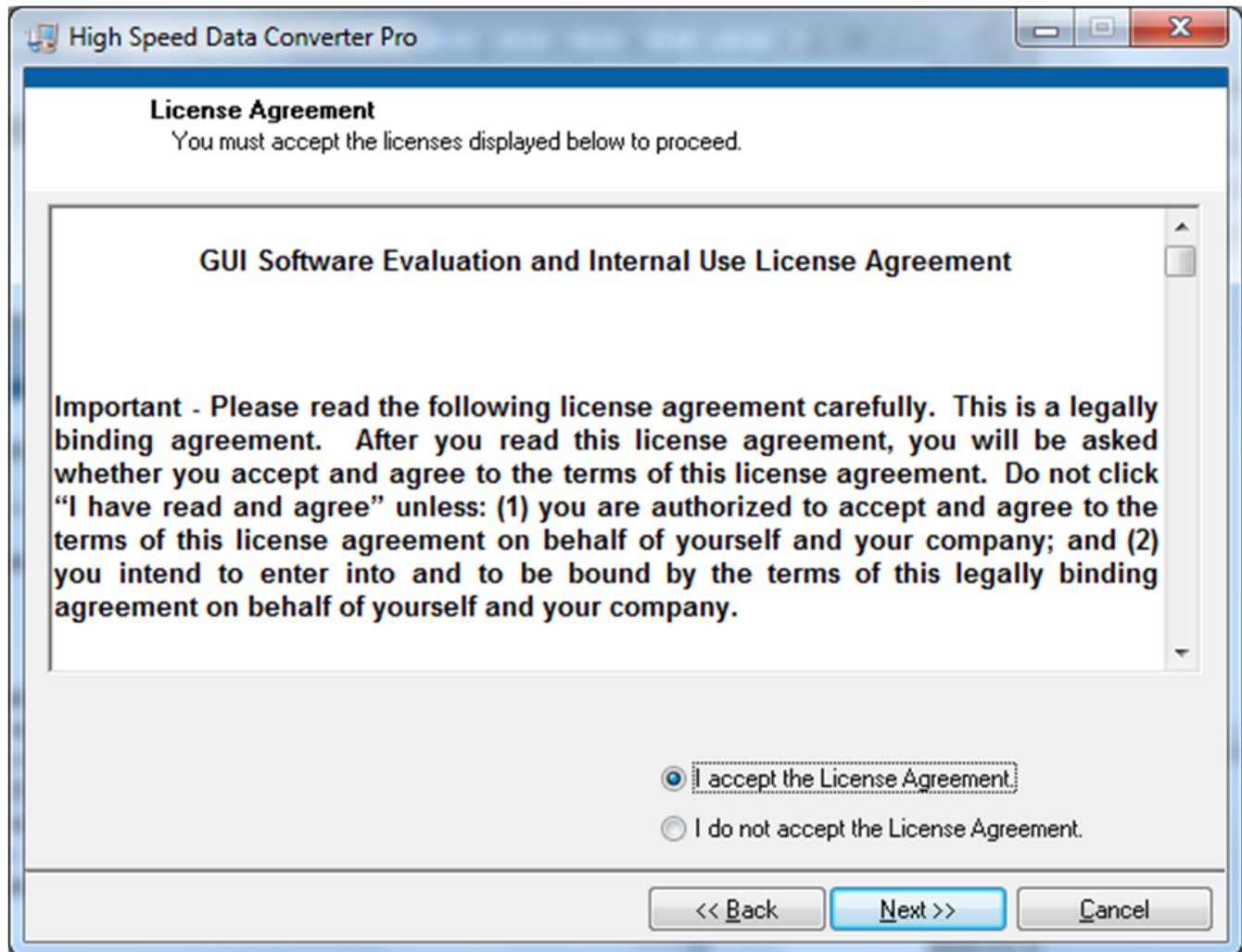


Figure 42. HSDCPro Install (TI License Agreement)

- Read the License Agreement from National Instruments and select *I accept the License Agreement* and press the *Next* button as shown in [Figure 43](#).

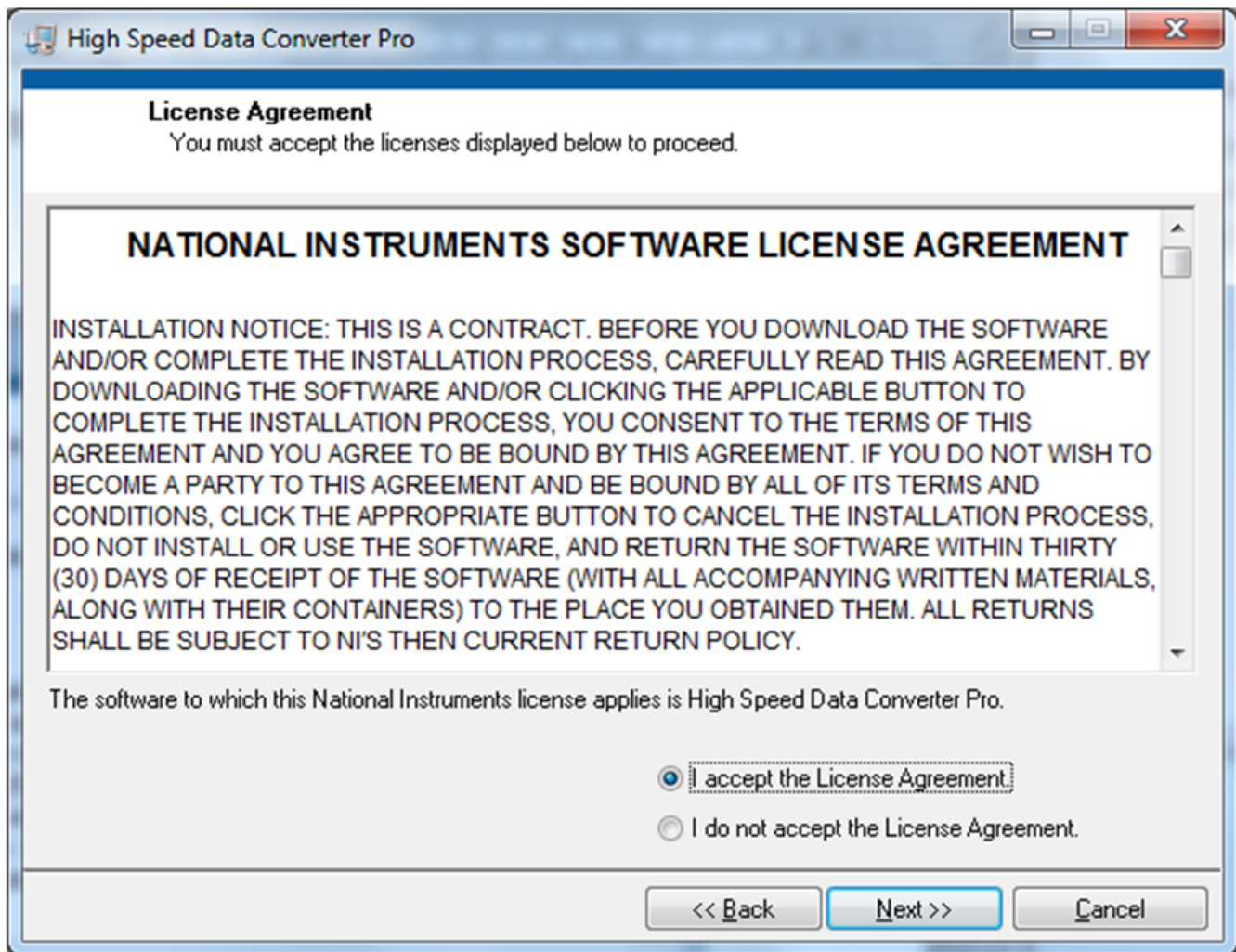


Figure 43. HSDCPro Install (NI License Agreement)

- Press the *Next* button as shown in [Figure 44](#).

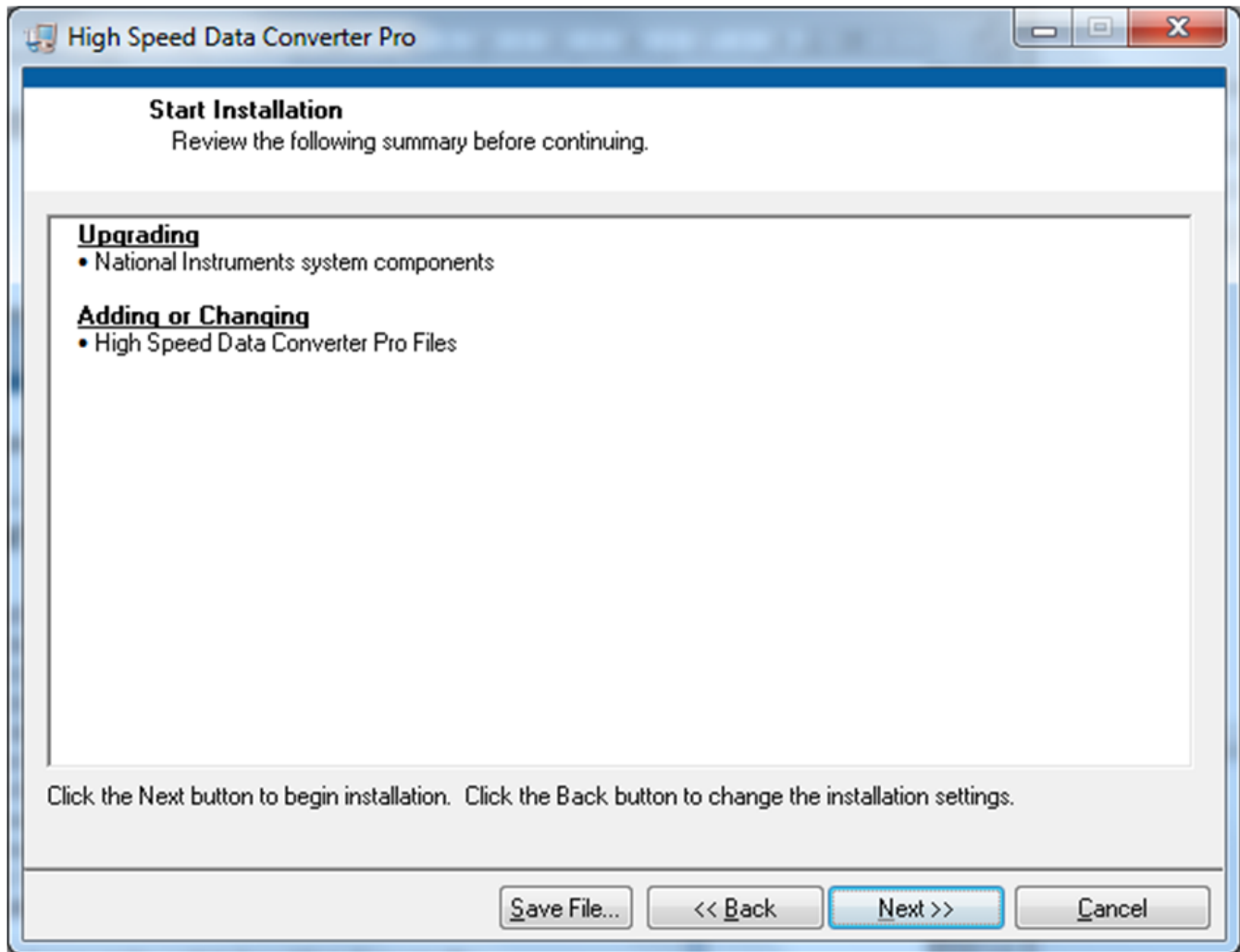


Figure 44. HSDCPro Install (Start Installation)

- The window shown in [Figure 45](#) should appear indicating that the installation is in progress.

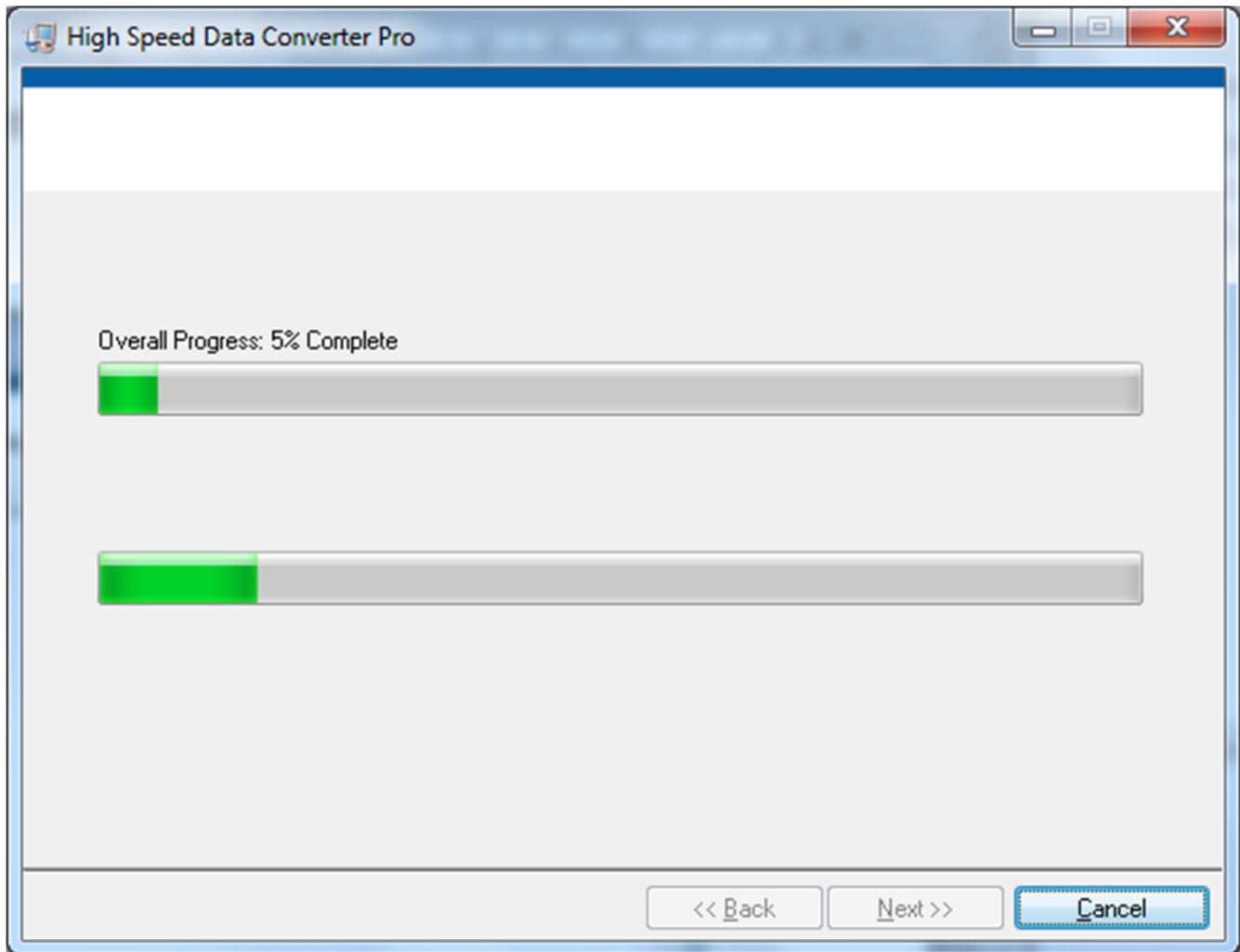


Figure 45. HSDCPro Install (Installation Progress)

- The window shown in [Figure 46](#) appears indicating *Installation Complete*. Press the *Next* button.

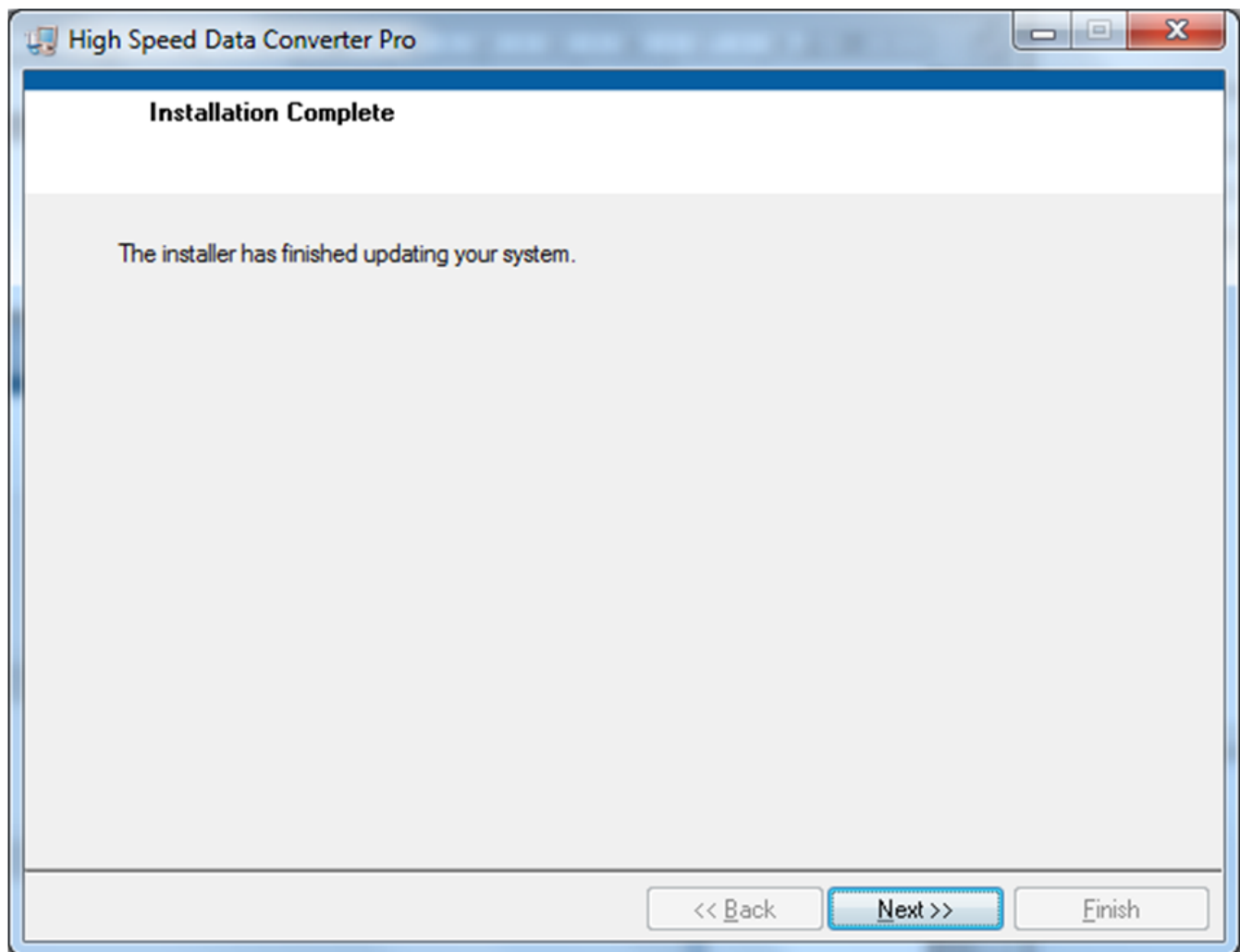


Figure 46. HSDCPro Install (Installation Complete)

- The window shown in [Figure 47](#) appears briefly to complete the process.

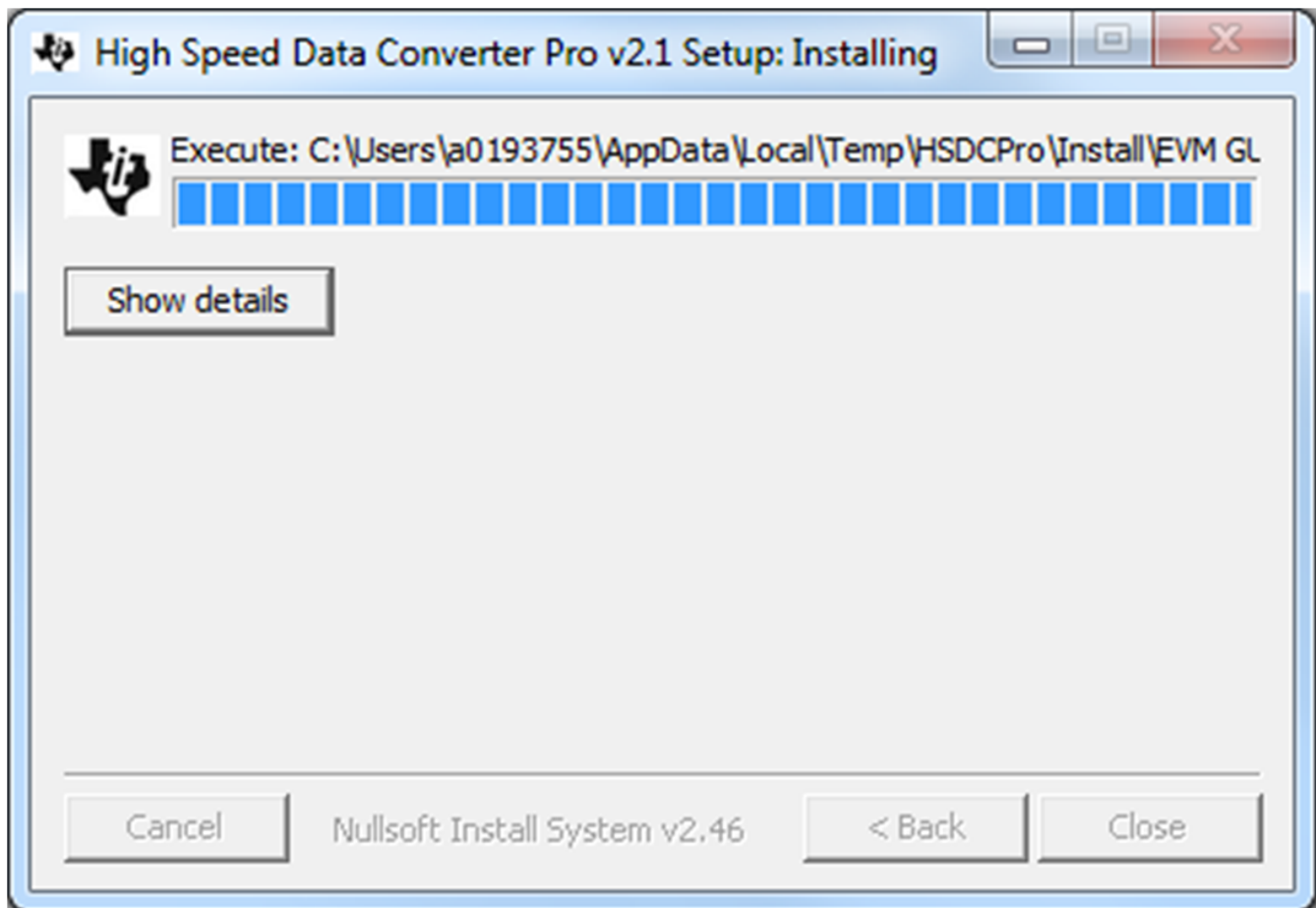


Figure 47. HSDCPro Install (h)

- As shown in Figure 48 a restart might be requested depending on whether or not the PC already had the National Instruments MCR Installer. If requested, hit the *Restart* button to complete the installation.

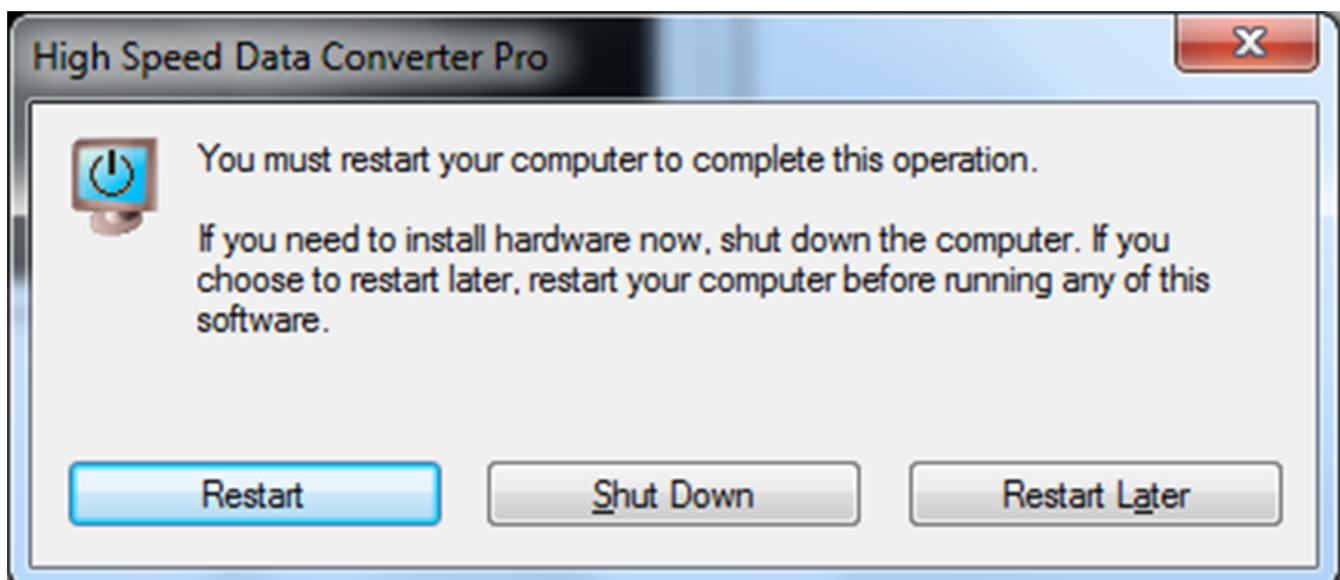


Figure 48. HSDCPro Install

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1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, or documentation (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms and conditions set forth herein. Acceptance of the EVM is expressly subject to the following terms and conditions.
 - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductors products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms and conditions that accompany such Software
 - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
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 - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for any defects that are caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI. Moreover, TI shall not be liable for any defects that result from User's design, specifications or instructions for such EVMs. Testing and other quality control techniques are used to the extent TI deems necessary or as mandated by government requirements. TI does not test all parameters of each EVM.
 - 2.3 If any EVM fails to conform to the warranty set forth above, TI's sole liability shall be at its option to repair or replace such EVM, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.
3. *Regulatory Notices:*
 - 3.1 *United States*
 - 3.1.1 *Notice applicable to EVMs not FCC-Approved:*

This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
 - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

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3.3.1 *Notice for EVMs delivered in Japan:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan are NOT certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, User is required by Radio Law of Japan to follow the instructions below with respect to EVMs:

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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東京都新宿区西新宿 6 丁目 2 4 番 1 号

西新宿三井ビル

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4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

4.3 *Safety-Related Warnings and Restrictions:*

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